

NOIL2SM1300A

LUPA1300-2: High Speed CMOS Image Sensor

Features

- 1280 x 1024 Active Pixels
- 14 μm X 14 μm Square Pixels
- 1.4" Optical Format
- Monochrome or Color Digital Output
- 500 fps Frame Rate
- On-Chip 10-Bit ADCs
- 12 LVDS Serial Outputs
- Random Programmable ROI Readout
- Pipelined and Triggered Global Shutter
- On-Chip Column FPN Correction
- Serial Peripheral Interface (SPI)
- Limited Supplies: Nominal 2.5 V and 3.3 V
- -50°C to $+85^{\circ}\text{C}$ Operational Temperature Range
- 168-Pin μPGA Package
- Power Dissipation: 1350 mW
- These Devices are Pb-Free and are RoHS Compliant

Applications

- High Speed Machine Vision
- Motion Analysis
- Intelligent Traffic System
- Medical Imaging
- Industrial Imaging

Description

The LUPA1300-2 is an integrated SXGA high speed, high sensitivity CMOS image sensor. This sensor targets high speed machine vision and industrial monitoring applications. The LUPA1300-2 sensor runs at 500 fps and has triggered and pipelined shutter modes. It packs 24 parallel 10-bit A/D converters with an aggregate conversion rate of 740 MSPS. On-chip digital column FPN correction enables the sensor to output ready to use image data for most applications. To enable simple and reliable system integration, the 12 channels, 1 sync channel, 8 Gbps, and LVDS serial link protocol supports skew correction and serial link integrity monitoring.

The peak responsivity of the 14 μm x 14 μm 6T pixel is 63 DN/nJ/cm². Dynamic range is measured at 57 dB. In full frame video mode, the sensor consumes 1350 mW from the 2.5 V and 3.3 V power supplies. The sensors integrate A/D



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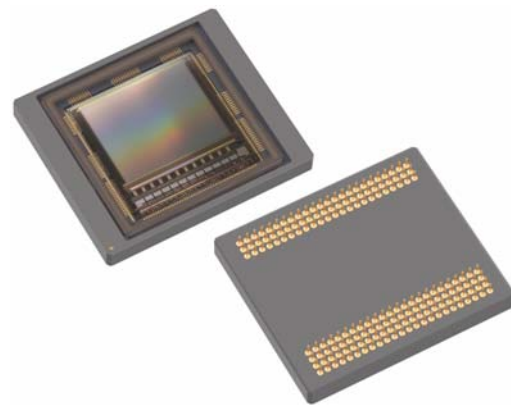


Figure 1. LUPA1300-2 Die Photo

conversion, on-chip timing for a wide range of operating modes, and has an LVDS interface for easy system integration.

By removing the visually disturbing column patterned noise, this sensor enables building a camera without any offline correction or the need for memory. In addition, the on-chip column FPN correction is more reliable than an offline correction, because it compensates for supply and temperature variations. The sensor requires one master clock for operations up to 500 fps.

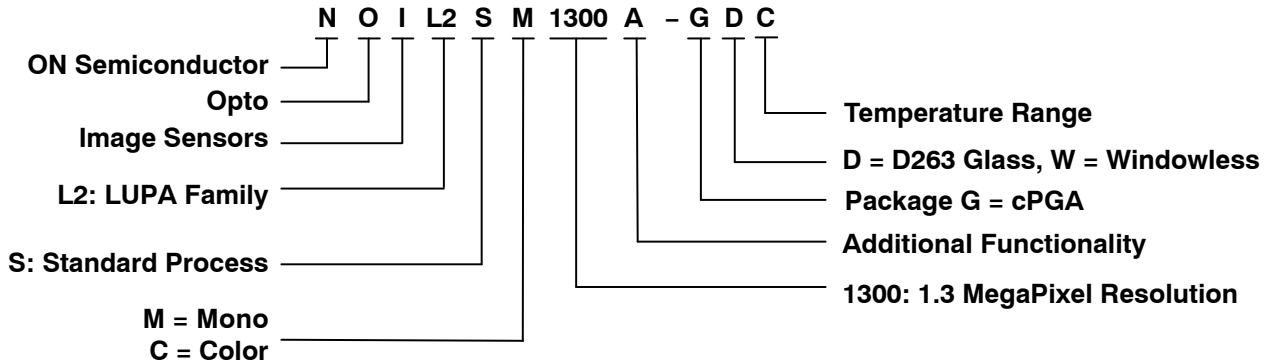
The LUPA1300-2 is housed in a 168 pin μPGA package and is available in a monochrome version and Bayer (RGB) patterned color filter array. The monochrome version is also available without glass. Contact your local ON Semiconductor office.

NOIL2SM1300A

ORDERING INFORMATION

| Marketing Part Number | Description | Package |
|-----------------------|--------------------|-------------------|
| NOIL2SM1300A-GDC | Mono with Glass | 168 pin μ PGA |
| NOIL2SM1300A-GWC | Mono without Glass | |
| NOIL2SC1300A-GDC | Color with Glass | |

ORDERING CODE DEFINITION



PRODUCT PACKAGE MARK

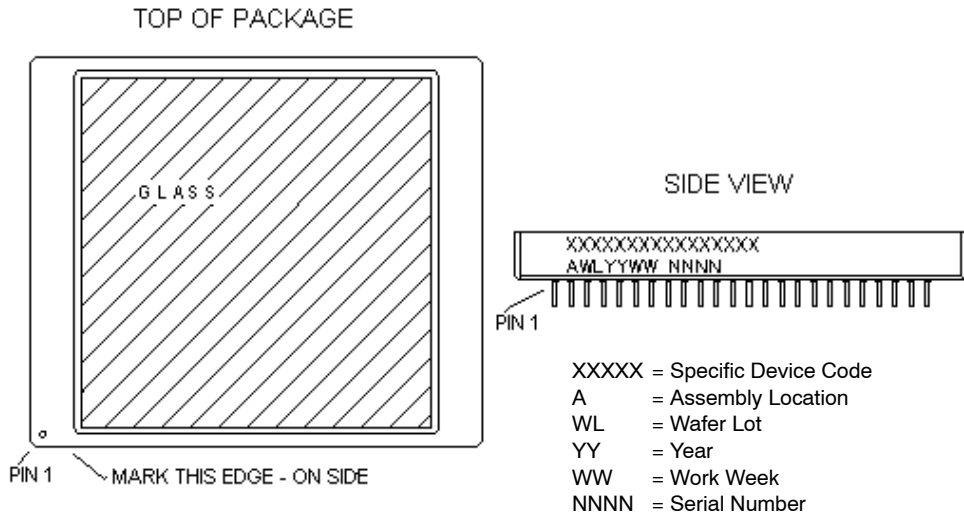


Figure 2. Marking Diagram

Line 1: NOIL2Sx1300A-GyC where x denotes M = mono and C = color; y denotes D = D263 glass and W = windowless.
 Line 2: **AWLYYWW** where AWL is PRODUCTION lot traceability, YYWW is the 4-digit date code

NOIL2SM1300A

SPECIFICATIONS

Key Specifications

Table 1. GENERAL SPECIFICATIONS

| Parameter | Specifications |
|------------------------|--|
| Active Pixels | 1280 (H) x 1024 (V) |
| Pixel Size | 14 μm x 14 μm |
| Pixel Type | 6T pixel architecture |
| Pixel Rate | 630 Mbps per channel (12 serial LVDS outputs) |
| Shutter Type | Pipelined and Triggered Global Shutter |
| Frame Rate | 500 fps at 1.3 Mpixel (boosted by subsampling and windowing) |
| Master Clock | 315 MHz for 500 fps |
| Windowing (ROI) | Randomly programmable ROI read out up to four multiple windows |
| Read Out | Windowed, flipped, mirrored, and subsampled readout possible |
| ADC Resolution | 10-bit, on-chip |
| Extended Dynamic Range | Multiple slope (up to 90 dB optical dynamic range) |

Table 2. ELECTRO-OPTICAL SPECIFICATIONS

| Parameter | Value |
|-----------------------------|--|
| Conversion gain | 0.0325 LSB ₁₀ /e ⁻ |
| Full well charge | 30 ke ⁻ |
| Responsivity | 63 LSB ₁₀ /nJ/cm ² at 550 nm |
| Fill factor | 40% |
| Parasitic light sensitivity | < 1/10,000 |
| Dark noise | 1.2025 LSB ₁₀ |
| QE x FF | 35% at 550 nm |
| FPN | 2% RMS of the output swing |
| PRNU | < 1% RMS of the output signal |
| Dark signal | 162 LSB ₁₀ /s, 5000 e ⁻ /s |
| Power dissipation | 1350 mW |

Absolute Maximum Ratings

Table 3. ABSOLUTE MAXIMUM RATINGS (Note 1)

| Symbol | Description | Min | Max | Units |
|--------------------------------|------------------------------------|------|------|-------|
| ABS (2.5 V supply group) | ABS rating for 2.5 V supply group | -0.5 | 3.0 | V |
| ABS (3.3 V supply group) | ABS rating for 3.3 V supply group | -0.5 | 4.3 | V |
| ABS (3.5 V supply group) | ABS rating for 3.5 V supply group | -0.5 | 4.3 | V |
| ESD (Note 3) | HBM | 2000 | | V |
| | CDM | 500 | | V |
| LU | Latchup | 200 | | mA |
| T _S (Notes 4 and 5) | ABS Storage temperature range | -40 | +150 | °C |
| | ABS Storage humidity range at 85°C | | 85 | %RH |

RECOMMENDED OPERATING RATINGS

| | | | | |
|--------------------------------|-----------------------------|-----|-----|----|
| T _J (Notes 2 and 5) | Operating temperature range | -50 | +85 | °C |
|--------------------------------|-----------------------------|-----|-----|----|

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Absolute maximum ratings are limits beyond which damage may occur.
2. Operating ratings are conditions at which operation of the device is intended to be functional.
3. ON Semiconductor recommends that our customers become familiar with, and follow the procedures in JEDEC Standard JESD625-A. Refer to Application Note AN52561. Long term exposure toward the maximum storage temperature will accelerate color filter degradation.
4. Caution needs to be taken to avoid dried stains on the underside of the glass due to condensation. The glass lid glue is permeable and can absorb moisture if the sensor is placed in a high % RH environment.
5. HTS – High Temperature Storage was successfully completed on LUPA 1300-2 color devices at +150°C for 500 hours. Temperature Cycling was successfully completed from -40°C to +125°C up to 1000 cycles. No reliability stress has been performed at -50°C.

NOIL2SM1300A

Electrical Specifications

Table 4. POWER SUPPLY RATINGS (Notes 1, 2 and 3)

Boldface limits apply for $T_J = T_{MIN}$ to T_{MAX} , all other limits $T_J = +30^\circ\text{C}$. Clock = 315 MHz

| Symbol | Power Supply | Parameter | Condition | Min | Typ | Max | Units |
|----------------------------------|------------------------------|-------------------------|---|------------|-----|------------|-------|
| V_{ANA} , GND_{ANA} | Analog Supply | Operating Voltage | | -5% | 2.5 | +5% | V |
| | | Dynamic Current | Clock enabled, lux = 0 | | 7 | 20 | mA |
| | | Peak Current | Clock enabled, lux = 0 | | 16 | | mA |
| | | Standby Current | Shutdown mode, lux = 0 | | 1 | | mA |
| V_{DIG} , GND_{DIG} | Digital Supply | Operating Voltage | | -5% | 2.5 | +5% | V |
| | | Dynamic Current | Clock enabled, lux = 0 | | 80 | 120 | mA |
| | | Peak Current | Clock enabled, lux = 0 | | 130 | | |
| | | Standby Current | Shutdown mode, lux = 0 | | 52 | | mA |
| V_{PIX} , GND_{PIX} | Pixel Supply | Operating Voltage | | -5% | 2.5 | +5% | V |
| | | Dynamic Current | Clock enabled, lux = 0 | | 6 | 50 | mA |
| | | Peak Current during FOT | Clock enabled, lux = 0, transient duration = 9 μs | | 1.4 | | A |
| | | Peak Current during ROT | Clock enabled, lux = 0, transient duration = 2.5 μs | | 35 | | mA |
| | | Standby Current | Shutdown mode, lux = 0 | | 1 | | mA |
| V_{LVDS} , GND_{LVDS} | LVDS Supply | Operating Voltage | | -5% | 2.5 | +5% | V |
| | | Dynamic Current | Clock enabled, lux = 0 | | 220 | 275 | mA |
| | | Peak Current | Clock enabled, lux = 0 | | 280 | | mA |
| | | Standby Current | Shutdown mode, lux = 0 | | 100 | | mA |
| V_{ADC} , GND_{ADC} | ADC Supply | Operating Voltage | | -5% | 2.5 | +5% | V |
| | | Dynamic Current | Clock enabled, lux = 0 | | 210 | 275 | mA |
| | | Peak Current | Clock enabled, lux = 0 | | 260 | | mA |
| | | Standby Current | Shutdown mode, lux = 0 | | 3 | | mA |
| V_{BUF} , GND_{BUF} | Buffer Supply | Operating Voltage | | -5% | 2.5 | +5% | V |
| | | Dynamic Current | Clock enabled, lux = 0 | | 30 | 50 | mA |
| | | Peak Current | Clock enabled, lux = 0 | | 85 | | mA |
| | | Standby Current | shutdown mode, lux = 0 | | 0.1 | | mA |
| V_{SAMPLE} , GND_{SAMPLE} | Sampling Circuitry Supply | Operating Voltage | | -5% | 2.5 | +5% | V |
| | | Dynamic Current | Clock enabled, lux = 0 | | 2 | | mA |
| | | Peak Current | Clock enabled, lux = 0 | | 42 | | mA |
| | | Standby Current | Shutdown mode, lux = 0 | | 1 | | mA |
| V_{RES} | Reset Supply | Operating Voltage | | -5% | 3.5 | +5% | V |
| | | Dynamic Current | Clock enabled, lux = 0 | | 2 | 15 | mA |
| | | Peak Current | Clock enabled, lux = 0 | | 65 | | mA |
| | | Standby Current | Shutdown mode, lux = 0 | | 2 | | mA |

1. All parameters are characterized for DC conditions after thermal equilibrium is established.
2. The peak currents were measured without the load capacitor from the LDO (Low Dropout Regulator). The 100 nF capacitor bank was connected to the pin in question.
3. This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields. However, it is recommended that normal precautions be taken to avoid application of any voltages higher than the maximum rated voltages to this high-impedance circuit.
4. The V_{RES_AB} and V_{PRECH} power supply should be designed to have a sourcing and sinking current capability for frame rates of the order of 20k frames /sec.

NOIL2SM1300A

Table 4. POWER SUPPLY RATINGS (Notes 1, 2 and 3)

Boldface limits apply for $T_J = T_{MIN}$ to T_{MAX} , all other limits $T_J = +30^{\circ}C$. Clock = 315 MHz

| Symbol | Power Supply | Parameter | Condition | Min | Typ | Max | Units |
|---------------------------------|----------------------------------|-----------------------------------|-----------------------------|-------------|-----|--------------|-------|
| V _{RES_AB} (Note 4) | Antiblooming Supply | Operating Voltage | | -10% | 0.7 | +10% | V |
| | | Dynamic Current | Clock enabled, lux = 0 | | 1 | | mA |
| | | Peak Current following edge reset | Clock enabled, lux = 0 | | 50 | | mA |
| | | Standby Current | Shutdown mode, lux = 0 | | 1 | | mA |
| V _{RES_DS} | Reset Dual Slope Supply | Operating Voltage | | 1.8 | 2.5 | 3.675 | V |
| | | Dynamic Current | Clock enabled, lux = 0 | | 0.4 | 3 | mA |
| | | Peak Current | Clock enabled, lux = 0 | | 36 | | mA |
| V _{RES_TS} | Reset Triple Slope Supply | Operating Voltage | | 1.8 | 2.2 | 3.675 | V |
| | | Dynamic Current | Clock enabled, lux = 0 | | 0.3 | 2 | mA |
| | | Peak Current | Clock enabled, lux = 0 | | 14 | | mA |
| V _{MEM_L} | Memory Element low level supply | Operating Voltage | | -5% | 2.5 | +5% | V |
| | | Dynamic Current | Clock enabled, lux = 0 | | 0.2 | 1 | mA |
| | | Peak Current during FOT | Clock enabled, lux = 0 | | 62 | | mA |
| | | Peak Current during FOT | Clock enabled, bright | | 30 | | mA |
| V _{MEM_H} | Memory Element high level supply | Operating Voltage | | -5% | 3.3 | +5% | V |
| | | Dynamic Current | Clock enabled, lux = 0 | | 1 | | mA |
| | | Peak Current during FOT | Clock enabled, lux = 0 | | 45 | | mA |
| V _{PRECH} (Note 4) | Pre_charge Driver Supply | Operating Voltage | | -10% | 0.7 | +10% | V |
| | | Dynamic Current | Clock enabled, lux = 0 | | 0.3 | 3 | mA |
| | | Peak Current during FOT | Clock enabled, lux = 0 | | 32 | | mA |
| | | Peak Current during FOT | Clock enabled, lux = bright | | 25 | | mA |

1. All parameters are characterized for DC conditions after thermal equilibrium is established.
2. The peak currents were measured without the load capacitor from the LDO (Low Dropout Regulator). The 100 nF capacitor bank was connected to the pin in question.
3. This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields. However, it is recommended that normal precautions be taken to avoid application of any voltages higher than the maximum rated voltages to this high-impedance circuit.
4. The V_{RES_AB} and V_{PRECH} power supply should be designed to have a sourcing and sinking current capability for frame rates of the order of 20k frames /sec.

Every module in the image sensor has its own power supply and ground. The grounds can be combined externally, but not all power supply inputs may be combined. Some power supplies must be isolated to reduce electrical crosstalk and improve shielding, dynamic range, and output swing. Internal to the image sensor, the ground lines of each module are kept separate to improve shielding and electrical crosstalk between them.

The LUPA1300-2 contains circuitry to protect the inputs against damage due to high static voltages or electric fields. However, take normal precautions to avoid voltages higher

than the maximum rated voltages in this high impedance circuit. Unused inputs must always be tied to an appropriate logic level, for example, V_{DD} or GND. All cap_XXX pins must be connected to ground through a 100 nF capacitor.

The recommended combinations of supplies are:

- Analog group of +2.5 V supply: V_{SAMPLE}, V_{RES_DS}, V_{MEM_L}, V_{ADC}, V_{pix}, V_{ANA}, V_{BUF}
- Digital Group of +2.5 V supply: V_{DIG}, V_{LVDS}
- Combine V_{PRECH} and V_{RES_AB} to one supply (Note 4)

Table 5. POWER DISSIPATION (Note 1)

Power supply specifications according to Table 4.

| Symbol | Parameter | Condition | Typ | Units |
|------------------------|---------------------------|-----------------------------------|------|-------|
| Power _{STDBY} | Standby Power | Blocks in standby with SPI upload | 400 | mW |
| Power | Average Power Dissipation | lux = 0, clock = 315 MHz, 500 fps | 1350 | mW |

NOIL2SM1300A

Table 6. AC ELECTRICAL CHARACTERISTICS (Note 1)

The following specifications apply for VDD = 2.5 V, Clock = 315 MHz, 500 fps.

| Symbol | Parameter | Condition | Typ | Max | Units |
|-------------------|-----------------------|---------------------|-----|-----|-------|
| F _{CLK} | Input Clock Frequency | fps = 500 | | 315 | MHz |
| DC _{CLK} | Clock Duty Cycle | At maximum clock | 50 | | % |
| DCD | Duty Cycle Distortion | At maximum clock | | 250 | ps |
| | Jitter | peak-to-peak | 50 | | ps |
| fps | Frame Rate | Maximum clock speed | | 500 | fps |

NOTE: Duty Cycle Distortion and Jitter is passed directly from input to output. Therefore, DCD and Jitter tolerance depends on the customer's system clock generation circuitry.

OVERVIEW

This data sheet describes the interface of the LUPA1300-2 image sensor. The SXGA resolution CMOS active pixel sensor features synchronous shutter and a maximal frame rate of 500 fps in full resolution. The readout speed is boosted by sub sampling and the windowed region of interest (ROI) readout. FPN correction cannot be used in conjunction with sub-sampling and windowed region of interest readout for windows starting with non zero kernel address. High dynamic range scenes can be captured using the double and multiple slope functionality. User programmable row and column start and stop positions enables windowing. Sub sampling reduces resolution while maintaining the constant field of view and an increased frame rate.

The LUPA1300-2 sensor has 12 LVDS high speed outputs that transfer image data over longer distances. This simplifies the surrounding system. The LVDS interface can

receive high speed and wide bandwidth data signals and maintain low noise and distortion. A special training mode enables the receiving system to synchronize the incoming data stream when switching to master, slave, or triggered mode. The image sensor also integrates a programmable offset and gain amplifier for each channel.

A 10-bit ADC converts the analog signal to a 10-bit digital word stream. The sensor uses a 3-wire Serial Peripheral Interface (SPI). It requires only one master clock for operation up to 500 fps.

The sensor is available in a monochrome version or Bayer (RGB) patterned color filter array. It is placed in a 168-pin ceramic μ PGA package.

Figure 2 depicts the photovoltaic response of the LUPA1300-2. Figure 3 shows the spectral response for the mono and color versions of LUPA1300-2.

Photovoltaic Response Curve

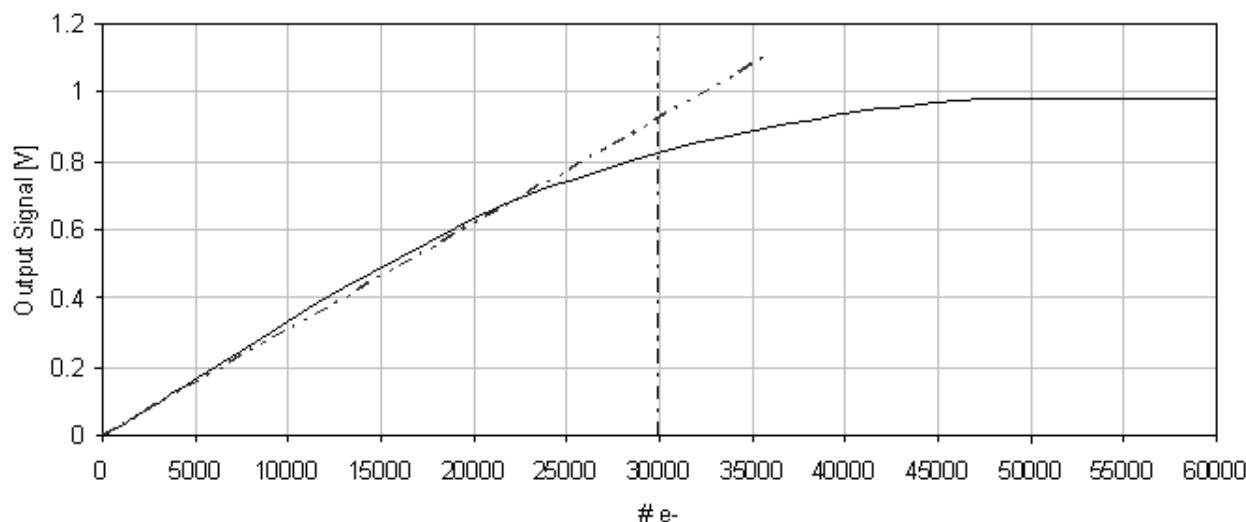


Figure 3. Photovoltaic Response of LUPA1300-2

NOIL2SM1300A

Spectral Response Curve

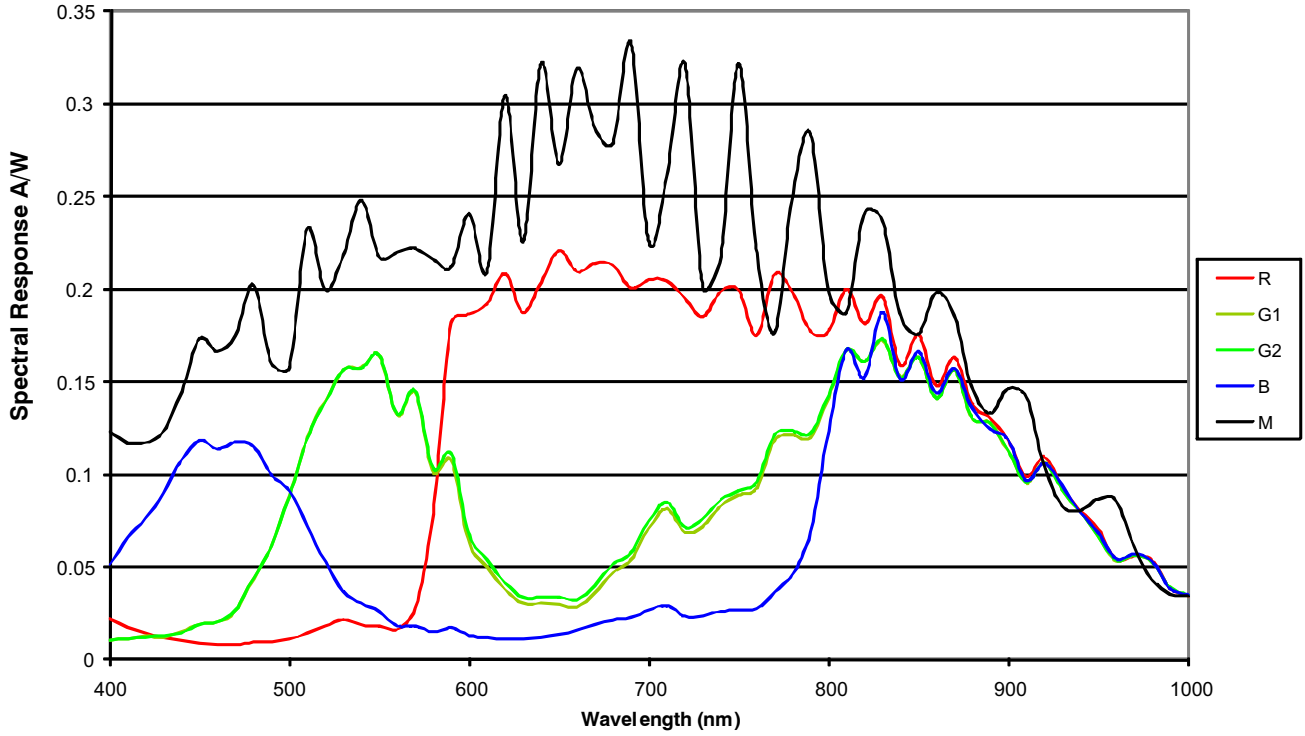


Figure 4. Spectral Response of LUPA1300-2 Mono and Color

Color Filter Array

The color version of LUPA1300-2 is available in Bayer (RGB) patterned color filter array. The orientation of RGB is shown in Figure 4.

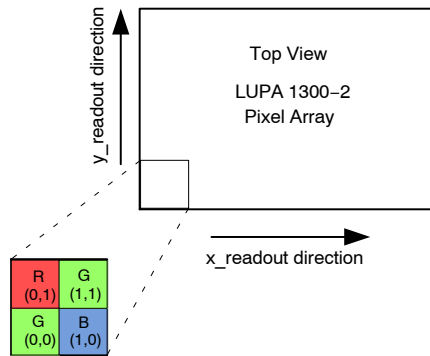


Figure 5. RGB Bayer

SENSOR ARCHITECTURE

Image Sensor Core

The floor plan of the architecture is shown in Figure 5. The sensor consists of a pixel array, analog front end, data block, and LVDS transmitters and receivers. Separate modules for the SPI, clock division, and sequencer are also integrated. The image sensor of 1280 x 1024 active pixels is read out in progressive scan.

This architecture enables programmable addressing in the x-direction in steps of 24 pixels, and in the y-direction in steps of one pixel. The starting point of the address can be updated by the SPI.

The AFE prepares the signal for the digital data block when the data is multiplexed and prepared for the LVDS interface.

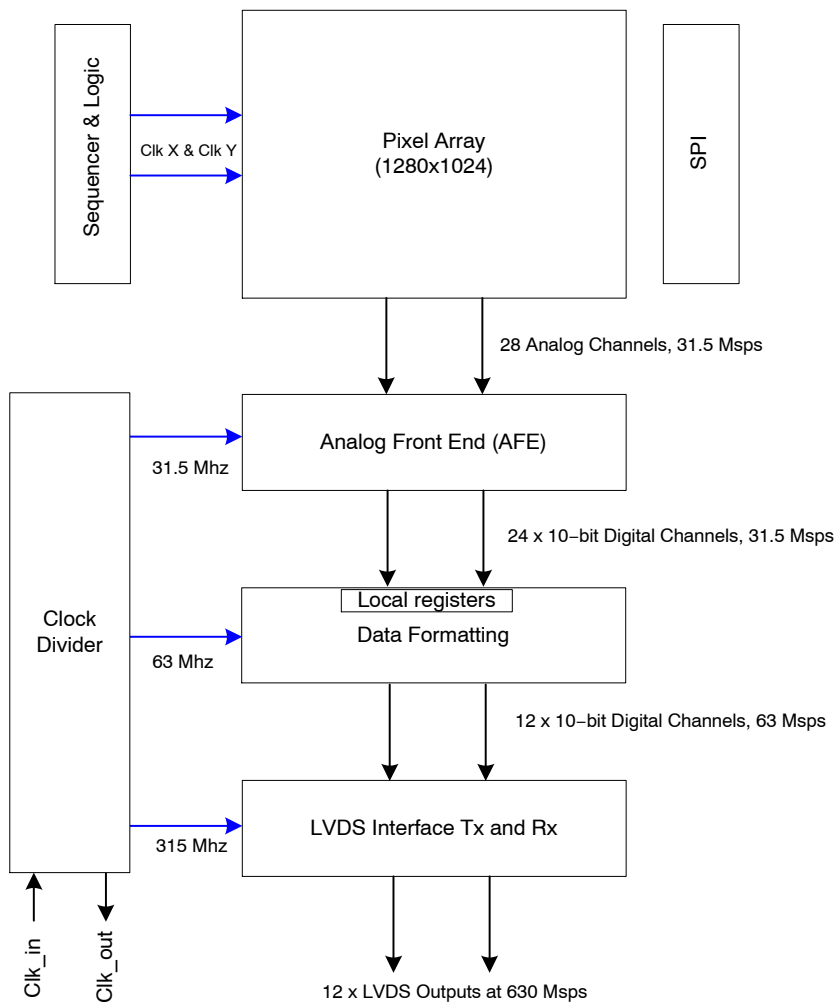


Figure 6. Floor Plan of the Sensor

The 6T Pixel

To obtain the global shutter feature combined with a high sensitivity and good parasitic light sensitivity (PLS), implement the pixel architecture shown in Figure 6. This pixel architecture is designed with a 14 μm x 14 μm pixel pitch to meet the specifications listed in Table 1 and Table 2 on page 3. This architecture also enables pipelined or triggered mode.

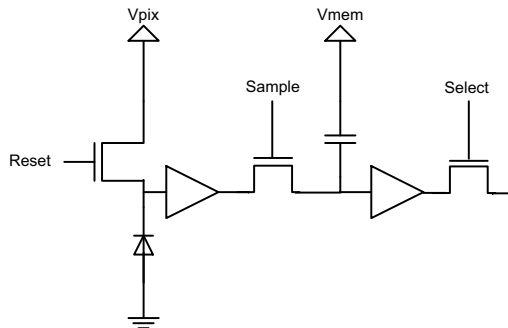


Figure 7. 6T Pixel Architecture

Analog Front End

Programmable Gain Amplifiers

The PGAs amplify the signal before sending it to the ADCs.

The amplification inside the PGA is controlled by one SPI setting: afemode [5:3].

Six gain steps can be selected by the afemode<5:3> register.

Table 7 lists the six gain settings. The unity gain selection of the PGA is done by the default afemode<5:3> setting.

Table 7. GAIN SETTINGS

| afemode<5:3> | Gain |
|--------------|------|
| 000 | 1 |
| 001 | 1.5 |
| 010 | 2 |
| 011 | 2.25 |
| 100 | 3 |
| 101 | 4 |

Analog to Digital Converter

The sensor has 24 10-bit pipelined ADCs on board. The ADCs nominally operate at 31.5 Msamples/s.

Table 8. ADC PARAMETERS

| Parameter | Specification |
|--------------|-----------------|
| Data rate | 31.5 Msamples/s |
| Quantization | 10 bit |
| DNL | Typ. < 1 DN |
| INL | Typ. < 1 DN |

Data Block

The data block is positioned in between the analog front end (output stage + ADCs) and the LVDS interface. It muxes the outputs of two ADCs to one LVDS block and performs some minor data handling:

- CRC calculation and insertion
- Training and test pattern generation

It also contains a huge part of the functionality for black level calibration and FPN correction.

A number of data blocks are placed in parallel to serve all data output channels. One additional channel generates the synchronization protocol. A high level overview is illustrated in the following figure.

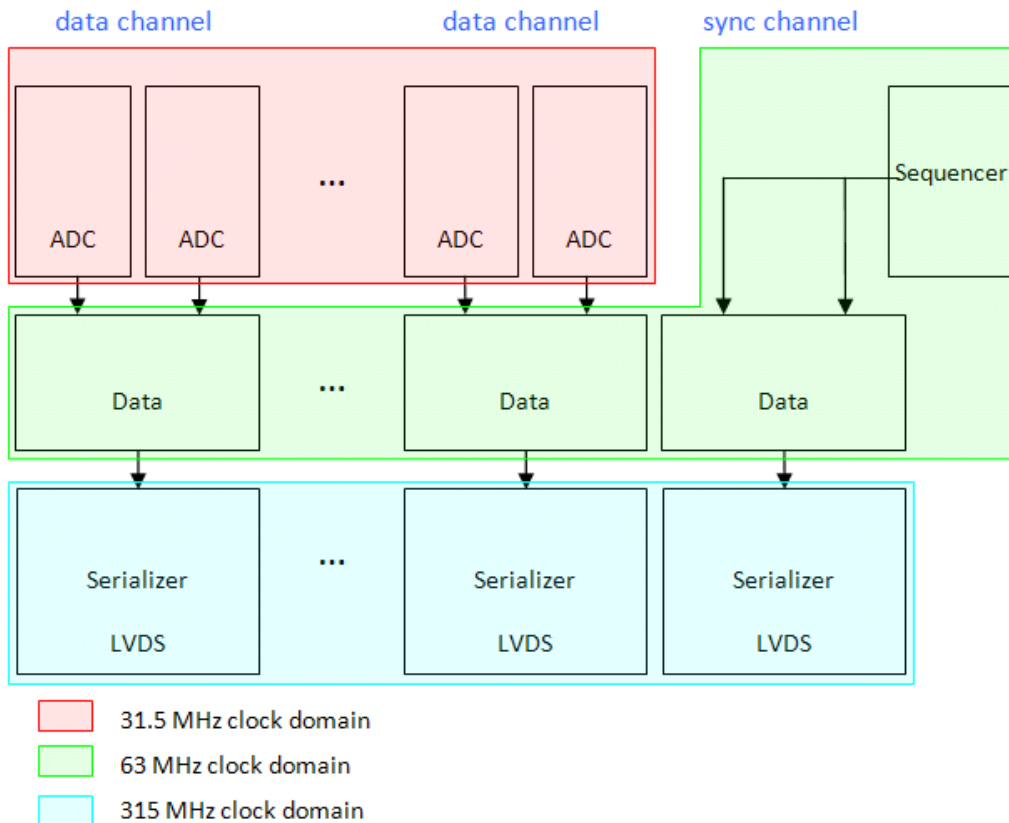


Figure 8. Data Block

LVDS Block

The LVDS block is positioned below the data block. It receives a differential clock signal, transmits differential data over the 12 data channels, and transmits a LVDS clock signal and a synchronization signal over the clock and synchronization channel.

A number of LVDS transmitter blocks are placed in parallel to serve all data, clock, and synchronization output channels. A high level overview is illustrated in the following figure.

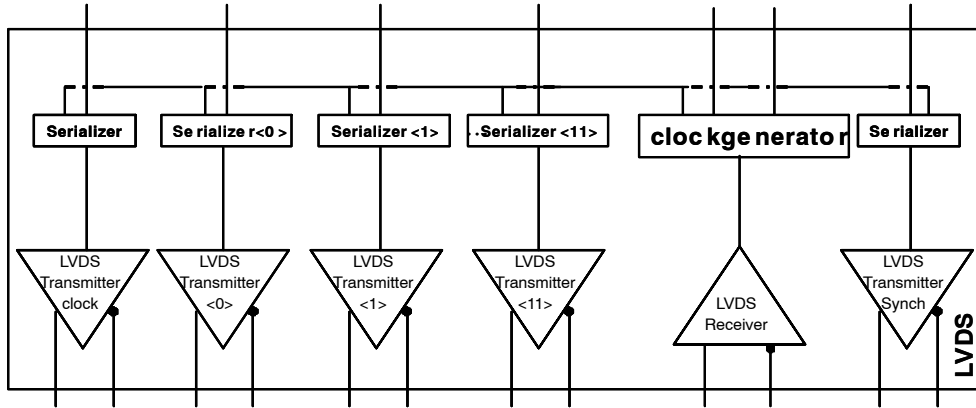


Figure 9. LVDS Block – High Level Overview

The function of this block is to take 10 bits of the protocol block, serialize these bits, and converts them to an LVDS standard (TIA/EIA 644A) compatible differential output signal. The block must also provide a clock to the host, to allow data recovery. This clock is an on-chip version of the clock coming from the host.

Sequencer and Logic

The sequencer generates the complete internal timing of the pixel array and the readout. The timing can be controlled by the user through the SPI register settings. The sequencer operates on the same clock as the data block. This is a division by 10 of the input clock (internally divided).

Table 9 lists the internal registers. These registers are discussed in detail in Detailed Description of Internal Registers on page 15.

Table 9. INTERNAL REGISTERS

| Block | Register Name | Address [6..0] | Field | Reset Value | Description |
|------------------|---------------|----------------|-------|-------------|-------------------------------------|
| MBS (reserved) | Fix1 | 0 | [7:0] | 0x00 | Reserved, fixed value |
| | Fix2 | 1 | [7:0] | 0xFF | Reserved, fixed value |
| | Fix3 | 2 | [7:0] | 0x00 | Reserved, fixed value |
| | Fix4 | 3 | [7:0] | 0x00 | Reserved, fixed value |
| | Fix5 | 4 | [7:0] | 0x08 | Reserved, fixed value |
| LVDS clk divider | lvdsmain | 5 | [3:0] | '0110' | lvds trim |
| | | | [7:4] | 0 | clkadc phase (recommended value: 3) |
| | lvdspwd1 | 6 | [7:0] | 0x00 | Power down channel 7:0 |
| | lvdspwd2 | 7 | [5:0] | 0 | Power down channel 13:8 |
| | | | [6] | 0 | Power down all channels |
| | | | [7] | 0 | lvds test mode |
| | Fix6 | 8 | [7:0] | 0x00 | Reserved, fixed value |
| AFE | afebias | 9 | [3:0] | '1000' | afe current biasing |
| | afemode | 10 | [2:0] | '111' | vrefp, vrefm settings |
| | | | [5:3] | '000' | Pga settings |
| | | | [6] | 0 | Power down AFE |
| | afepwd1 | 11 | [7:0] | 0x00 | Power down adc_channel_2x 7 to 0 |

NOIL2SM1300A

Table 9. INTERNAL REGISTERS

| Block | Register Name | Address [6..0] | Field | Reset Value | Description | |
|------------|----------------|----------------|-------|---|---|---|
| AFE | afepwd2 | 12 | [3:0] | 0x00 | Power down adc_channel_2x 11 to 8 | |
| Bias block | bandgap | 13 | [0] | '0' | Power down bandgap and currents | |
| | | | [1] | '1' | External resistor | |
| | | | [2] | '0' | External voltage reference | |
| | | | [5:3] | '000' | Bandgap trimming | |
| Image Core | imcmodes | 14 | [0] | 0 | Power down | |
| | | | [1] | '1' | Enable vrefcol regulator | |
| | | | [2] | '1' | Enable precharge regulator | |
| | | | [3] | 0 | Disable internal bias for vprech | |
| | | | [4] | '1' | Disable column load | |
| | | | [5] | '0' | clkmain invert | |
| | Fix7 | 15 | [7:0] | 0x00 | Reserved, fixed value | |
| | Fix8 | 16 | [7:0] | 0x00 | Reserved, fixed value | |
| | imcbias1 | 17 | [3:0] | '1000' | Bias colfn DAC buffer | |
| | | | | [7:4] | '1000' | Bias precharge regulator |
| | imcbias2 | 18 | [3:0] | '1000' | Bias pixel precharge level | |
| | | | | [7:4] | '1000' | Bias column ota |
| | imcbias3 | 19 | [3:0] | '1000' | Bias column unip fast | |
| | | | | [7:4] | '1000' | Bias column unip slow |
| | Imcbias4 | 20 | [3:0] | '1000' | Bias column load | |
| | | | | [7:4] | '1000' | Bias column precharge |
| Data Block | Fix9 | 21 | [7:0] | 0x20 | Reserved, fixed value | |
| | Fix10 | 22 | [7:0] | 0xC0 | Reserved, fixed value | |
| | dataconfig1 | 23 | [1:0] | 0x00 | Reserved, fixed value | |
| | | | | [2] | 1 | '1': Enables user upload of dacvrefadc register value '0': Keeps default value |
| | | | | [3] | 0 | Enable PRBS generation |
| | | | | [4] | 0 | Reserved, fixed value |
| | | | | [5] | 0 | Reserved, fixed value |
| | dataconfig2 | 24 | [7:0] | 0x03 | Training pattern inserted to sync LVDS receivers | |
| | | | | 0x2A | Training pattern inserted to sync LVDS receivers | |
| | Fix11 | 25 | [7:0] | 0 | Reserved, fixed value | |
| | dacvrefadc | 26 | [7:0] | 0x84 | Input to DAC to set the offset at the input of the ADC | |
| | Fix12 | 27 | [7:0] | 0x80 | Reserved, fixed value | |
| | Fix13 | 28 | [7:0] | | Reserved, fixed value | |
| | Fix14 | 29 | [7:0] | | Reserved, fixed value | |
| | datachannel0_1 | 30 | [0] | 0 | Bypass the data block | |
| | | | | [1] | 0 | Enables the FPN correction |
| [2] | | | | 0 | Overwrite incoming ADC data by the data in the testpat register | |
| [3] | | | | 0 | Reserved, fixed value | |
| | | [5:4] | 0x00 | Pattern inserted to generate a test image | | |

NOIL2SM1300A

Table 9. INTERNAL REGISTERS

| Block | Register Name | Address [6..0] | Field | Reset Value | Description |
|------------|----------------------|----------------|-------|-------------|---|
| Data Block | datachannel0_2 | 31 | [7:0] | 0x00 | Pattern inserted to generate a test image |
| | datachannel1_1 | 32 | [0] | 0 | Bypass the data block |
| | | | [1] | 0 | Enables the FPN correction |
| | | | [2] | 0 | Overwrite incoming ADC data by the data in the testpat register |
| | | | [3] | 0 | Reserved, fixed value |
| | | | [5:4] | 0x00 | Pattern inserted to generate a test image |
| | datachannel1_2 | 33 | [7:0] | 0x00 | Pattern inserted to generate a test image |
| | | | | | |
| | datachan- nel12_1 | 54 | [0] | 0 | Bypass the data block |
| | | | [1] | 0 | Enables the FPN correction |
| | | | [2] | 0 | Overwrite incoming ADC data by the data in the testpat register |
| | | | [3] | 0 | Reserved, fixed value |
| | | | [5:4] | 0x00 | Pattern inserted to generate a test image |
| | datachan- nel12_2 | 55 | [7:0] | 0x00 | Pattern inserted to generate a test image |
| Sequencer | seqmode1 | 56 | [0] | 1 | Enables sequencer for image capture |
| | | | [1] | 1 | '1': Master mode, integration timing is generated on-chip '0': Slave mode, integration timing is controlled off-chip through INT_TIME1, INT_TIME2 and INT_TIME3 pins |
| | | | [2] | 0 | '0': Pipelined mode '1': Triggered mode |
| | | | [3] | 0 | Enables('1')/disables('0') subsampling |
| | | | [4] | 0 | '1': Color subsampling scheme: 1:1:0:0:1:1:0:0 '0': B&W subsampling scheme: 1:0:1:0:1 |
| | | | [5] | 0 | Enable dual slope |
| | | | [6] | 0 | Enable triple slope |
| | | | [7] | 0 | Enables continued row select (that is, assert row select during pixel read out) |
| | seqmode2 | 57 | [4:0] | '10000' | Must be overwritten with '10001' to this register after startup, before readout. |
| | | | [6:5] | '00' | Number of active windows: "00": 1 window "01": 2 windows "10": 3 windows "11": 4 windows |
| | seqmode3 | 58 | [0] | '1' | Enables the generation of the CRC10 on the data and sync channels |
| | | | [1] | '0' | Enable readout black/grey columns |
| | | | [2] | '0' | Enable column fpn calibration/enable readout dummy line |
| | | | [5:3] | "001" | Number of frames in nondestructive read out: "000": invalid "001": one reset, one sample (default mode) "010": one reset, two samples ... |

NOIL2SM1300A

Table 9. INTERNAL REGISTERS

| Block | Register Name | Address [6..0] | Field | Reset Value | Description |
|-----------------|---------------|----------------|-------|--|--|
| Sequencer | | | [6] | 0 | Controls the granularity of the timer settings (only for those that have 'granularity selectable' in the description): '0': Expressed in number of lines '1': Expressed in clock cycles (multiplied by 2**seqmode4[3:0]) |
| | | | [7] | 0 | Allows delaying the syncing of events that happen outside of ROT to the next ROT. This avoids image artefacts. |
| | seqmode4 | 59 | [3:0] | 0x00 | Multiplier factor (=2**seqmode4[3:0]) for the timers when working in clock cycle mode |
| | | | [5:4] | 0x0 | Selects the source signals to put on the digital test pins (monitor pins): "00": integration time settings "01": EOS signals "10": frame sync signals "11": functional test mode |
| | | | [6] | '0' | Reverse read out in X direction |
| | | | [7] | '0' | Reverse read out in Y direction |
| | window1_1 | 60 | [7:0] | 0x00 | Y start address for window 1 |
| | window1_2 | 61 | [1:0] | 0x00 | Y start address for window 1 |
| | | | [7:2] | 0x00 | X start address for window 1 |
| | window1_3 | 62 | [7:0] | 0xFF | Y end address for window 1 |
| | window1_4 | 63 | [1:0] | 0x3 | Y end address for window 1 |
| | | | [7:2] | 0x36 | X width for window 1 |
| | window2_1 | 64 | [7:0] | 0x00 | Y start address for window 2 |
| | window2_2 | 65 | [1:0] | 0x00 | Y start address for window 2 |
| | | | [7:2] | 0x00 | X start address for window 2 |
| | window2_3 | 66 | [7:0] | 0xFF | Y end address for window 2 |
| | window2_4 | 67 | [1:0] | 0x3 | Y end address for window 2 |
| | | | [7:2] | 0x36 | X width for window 2 |
| | window3_1 | 68 | [7:0] | 0x00 | Y start address for window 3 |
| | window3_2 | 69 | [1:0] | 0x00 | Y start address for window 3 |
| | | | [7:2] | 0x00 | X start address for window 3 |
| | window3_3 | 70 | [7:0] | 0xFF | Y end address for window 3 |
| | window3_4 | 71 | [1:0] | 0x3 | Y end address for window 3 |
| | | | [7:2] | 0x36 | X width for window 3 |
| | window4_1 | 72 | [7:0] | 0x00 | Y start address for window 4 |
| | window4_2 | 73 | [1:0] | 0x00 | Y start address for window 4 |
| | | | [7:2] | 0x00 | X start address for window 4 |
| | window4_3 | 74 | [7:0] | 0xFF | Y end address for window 4 |
| | window4_4 | 75 | [1:0] | 0x3 | Y end address for window 4 |
| | | | [7:2] | 0x36 | X width for window 4 |
| | res_length1 | 76 | [7:0] | 0x02 | Length of pix_rst (granularity selectable) |
| | res_length2 | 77 | [7:0] | 0x00 | Length of pix_rst (granularity selectable) |
| res_dsts_length | 78 | [7:0] | 0x01 | Length of resetds and resetts (granularity selectable) | |
| tint_timer1 | 79 | [7:0] | 0xFF | Length of integration time (granularity selectable) | |
| tint_timer2 | 80 | [7:0] | 0x03 | Length of integration time (granularity selectable) | |

Table 9. INTERNAL REGISTERS

| Block | Register Name | Address [6..0] | Field | Reset Value | Description |
|-------|-------------------|----------------|-------|-------------|---|
| | tint_ds_timer1 | 81 | [7:0] | 0x40 | Length of DS integration time (granularity selectable) |
| | tint_ds_timer2 | 82 | [1:0] | 0x00 | Length of DS integration time (granularity selectable) |
| | tint_ts_timer1 | 83 | [7:0] | 0x0C | Length of TS integration time (granularity selectable) |
| | tint_ts_timer2 | 84 | [1:0] | 0x00 | Length of TS integration time (granularity selectable) |
| | tint_black_timer | 85 | [7:0] | 0x06 | Reserved, fixed value |
| | rot_timer | 86 | [7:0] | 0x09 | Length of ROT (granularity clock cycles) |
| | fot_timer | 87 | [7:0] | 0x3B | Length of FOT (granularity clock cycles) |
| | fot_timer | 88 | [1:0] | 0x01 | Length of FOT (granularity clock cycles) |
| | prechpix_timer | 89 | [7:0] | 0x7C | Length of pixel precharge (granularity clock cycles) |
| | prechpix_timer | 90 | [1:0] | 0x00 | Length of pixel precharge (granularity clock cycles) |
| | prechcol_timer | 91 | [7:0] | 0x03 | Length of column precharge (granularity clock cycles) |
| | rowselect_timer | 92 | [7:0] | 0x06 | Length of rowselect (granularity clock cycles) |
| | sample_timer | 93 | [7:0] | 0xF8 | Length of pixel_sample (granularity clock cycles) |
| | sample_timer | 94 | [1:0] | 0x00 | Length of pixel_sample (granularity clock cycles) |
| | vmem_timer | 95 | [7:0] | 0x10 | Length of pixel_vmem (granularity clock cycles) |
| | vmem_timer | 96 | [1:0] | 0x01 | Length of pixel_vmem (granularity clock cycles) |
| | delayed_rdt_timer | 97 | [7:0] | 0 | Readout delay for testing purposes (granularity selectable) |
| | delayed_rdt_timer | 98 | [7:0] | 0 | Readout delay for testing purposes (granularity selectable) |
| | Fix29 | 99 | [0] | 0 | Reserved, fixed value |
| | Fix30 | 100 | [0] | 0 | Reserved, fixed value |
| | Fix31 | 101 | [0] | 0 | Reserved, fixed value |
| | Fix32 | 102 | [0] | 0 | Reserved, fixed value |
| | Fix33 | 103 | [0] | 0 | Reserved, fixed value |
| | Fix34 | 104 | [0] | 0 | Reserved, fixed value |

Detailed Description of Internal Registers

The registers must be changed only during idle mode, that is, when seqmode1[0] is '0'. Uploaded registers have an immediate effect on how the frame is read out. Parameters uploaded during readout may have an undesired effect on the data coming out of the images.

MBS Block

The register block contains registers for sensor testing and debugging. All registers in this block must remain unchanged after startup.

LVDS Clock Divider Block

This block controls division of the input clock for the LVDS transmitters or receivers. This block also enables shutting down one or all LVDS channels. For normal operation, this register block must remain untouched after startup.

AFE Block

This register block contains registers to shut down ADC channels or the complete AFE block. This block also contains the register for setting the PGA gain: AFE_mode[5:3]. Refer to Absolute Maximum Ratings on page 3 for more details on the PGA settings.

Biasing Block

This block contains several registers for setting biasing currents for the sensor. Default values after startup must remain unchanged for normal operation of the sensor.

Image Core Block

The registers in this block have an impact on the pixel array itself. Default settings after startup must remain unchanged for normal operation of the image sensor.

Data Block

The data block is positioned in between the analog front end (output stage + ADCs) and the LVDS interface. It muxes the outputs of 2 ADCs to one LVDS block and performs some minor data handling:

- **CRC calculation and insertion.**
All data can be protected by a 10-bit checksum. The CRC10 is calculated over all pixels between a Line Start and a Line End. It is inserted in the data stream after the line is completed, if input seq_data_crc is enabled. The polynomial used is $(x^{10}+x^9+x^6+x^3+x^2+x+1)$ and 10 bits are calculated in parallel. When a new line is started, the seed is the first pixel value of a line. No CRC is calculated for that value. From then on, every incoming pixel is updated through the regular CRC.
- **Training and test pattern generation**

The most important registers in this block are:

Dataconfig. The dataconfig1[7:6] and dataconfig2[7:0] registers insert a training pattern in the LVDS channels to sync the LVDS receivers.

Datachannels. DatachannelX_1 and DatachannelX_2 (with X=0 to 12) are registers that allow you to enable or disable the FPN correction (DatachannelX_1[1]), and generate a test pattern if necessary (datachannelX_1[5:4] and datachannelX_2[7:0]).

Sequencer Block

The sequencer block group registers allow enabling or disabling image sensor features that are driven by the onboard sequencer. This block consists of the following registers:

Seqmode1. The seqmode1 registers have the following subregisters:

Seqmode1[0]: Enables sequencer for image capture, must be '1' during image acquisition.

Seqmode1[1]: This subregister has two modes:

'1': In this default mode the integration timing is generated on-chip.

'0': In this slave mode, the integration timing must be generated through the int_time1, int_time2, and int_time3 pins.

Seqmode1[2]: This bit enables pipelined (0) or triggered (1) mode.

Seqmode1[3]: Enable (1) or disable (0) subsampling.

Seqmode1[4]: This bit sets the type of subsampling scheme used when subsampling is enabled.

'1': Color (1:1:0:0:1:1:0:0:1...)

'0': Black and White (1:0:1:0:1)

Seqmode1[5]: This bit enables or disables the dual slope integration.

Seqmode1[6]: This bit enables or disables the triple slope integration.

Seqmode2. The seqmode2 register consists of only two subregisters:

Seqmode2[4:0]: Default value after startup is '10000', but this must be overwritten with the new value '10001' immediately after startup.

Seqmode2[6:5]: These two bits set the number of active windows:

'00': 1 window

'01': 2 windows

'10': 3 windows

'11': 4 windows (max)

Seqmode3. The seqmode3 register consists of the following subregisters:

Seqmode3[0]: This bit enables or disables the CRC10 generation on the data and sync channels

Seqmode3[1]: Not applicable

Seqmode3[2]: Enables or disables column FPN correction

Seqmode3[5:3]: Enables or disables, and sets the number of frames grabbed in nondestructive readout mode.

'000': Invalid

'001': Default, 1 reset, 1 sample

'010': 1reset, 2 samples

'011': 1 reset, 3 samples

Seqmode3[6]: Controls the granularity of the timer settings (only for those that have 'granularity selectable' in the description). As a result, all timer settings are set either in number of applied clock cycles, or in the number of 'readout lines'.

'0': expressed in number of lines

'1': expressed in clock cycles (multiplied by $2^{seqmode4[3:0]}$)

Seqmode3[7]: Allows syncing of events that happen outside of ROT to be delayed to the next ROT to avoid image artifacts.

Seqmode4. This register consists of four subregisters:

Seqmode4[3:0]: Multiplier factor ($2^{seqmode4[3:0]}$) for the timers when working in clock cycle mode.

Seqmode4[5:4]: Selects the source signals to be put on the digital test pins (monitor1, monitor2, and monitor3 pins)

"00": integration time settings

"01": EOS signals

"10": frame sync signals

"11": functional test mode

Seqmode4[6]: Enables (1) and disables (0) reverse X read out.

Seqmode4[7]: Enables (1) and disables (0) reverse Y read out.

Y1_start (60 and 61, 10 bit). These registers set the Y start address for window 1 (default window).

X1_start (61, 6bit). This register sets the X start address for window 1 (default window).

Y1_end (62 and 63, 10 bit). These registers set the Y end address for window 1 (default window).

X1_kernels (63, 6 bit). This register sets the number of kernels or X width to be read out for window 1 (default window).

Y2_start (64 and 65, 10 bit). These registers set the Y start address for window 2 (if enabled).

X2_start (65, 6bit). This register sets the X start address for window 2 (if enabled).

Y2_end (66 and 67, 10 bit). These registers set the Y end address for window 2 (if enabled).

X2_kernels (67, 6 bit). This register sets the number of kernels or X width to be read out for window 2 (if enabled).

Y3_start (68 and 69, 10 bit). These registers set the Y start address for window 3 (if enabled).

X3_start (69, 6bit). This register sets the X start address for window 3 (if enabled).

Y3_end (70 and 71, 10 bit). These registers set the Y end address for window 3 (if enabled).

X3_kernels (71, 6 bit). This register sets the number of kernels or X width to be read out for window 3 (if enabled).

Y4_start (72 and 73, 10 bit). These registers set the Y start address for window 4 (if enabled).

X4_start (73, 6bit). This register sets the X start address for window 4 (if enabled).

Y4_end (74 and 75, 10 bit). These registers set the Y end address for window 4 (if enabled).

X4_kernels (75, 6 bit). This register sets the number of kernels or X width to be read out for window 4 (if enabled).

Res_length (76 and 77). This register sets the length of the internal pixel array reset (how long are all pixel reset simultaneously). This value is expressed in 'number of lines' or in clock cycles (depends on seqmode3[6]).

Res_dsts_length. This register sets the length of the internal dual and triple slope reset pulses when enabled. This value is expressed in 'number of lines' or in clock cycles (depends on seqmode3[6]).

Tint_timer (79 and 80). This register sets the length of the integration time. This value is expressed in 'number of lines' or in clock cycles (depends on seqmode3[6]).

Tint_ds_timer (81 and 82). This register sets the length of the dual slope integration time. This value is expressed in 'number of lines' or in clock cycles (depends on seqmode3[6]).

Tint_ts_timer (83 and 84). This register sets the length of the triple slope integration time. This value is expressed in 'number of lines' or in clock cycles (depends on seqmode3[6]).

Serial Peripheral Interface (SPI)

The serial 4-wire interface (or SPI) uses a serial input or output to shift the data in or out the register buffer. The chip's configuration registers are accessed from the outside world through the SPI protocol. A 4-wire bus runs over the chip and connects the SPI I/Os with the internal register blocks. To upload the sensor, follow this sequence:

Disable Sequencer → Upload Sensor for new setting → Enable Sequencer

When sequencer is disabled, the training pattern appears on all the channels, including the sync. The interface consists of:

- cs_n: chip select, when LOW the chip is selected
- clk: the spi clock
- in: Master out, Slave in, the serial input of the register
- out: Master in, Slave out, the serial output of the register

SPI Protocol

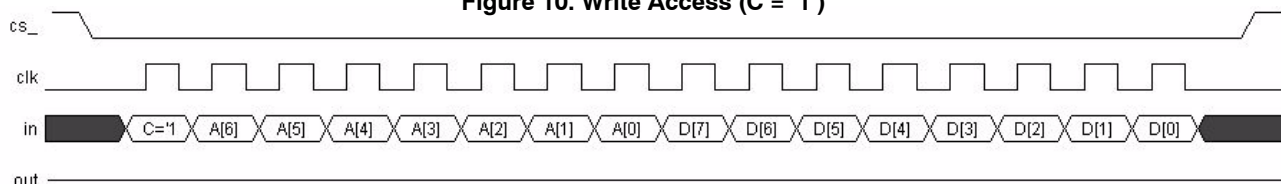
The information on the data 'in' line is:

- A command bit C, indicating a write ('1') or a read ('0') access
- 7-bit address
- 8-bit data word (in case of a write access)

The data 'out' line is generally in High Z mode, except when a read request is performed.

Data is always written on the bus on the falling edge of the clock, and sampled on the rising edge, as seen in Figure 9 and Figure 10. This is valid for both the 'in' and 'out' bus. The system clock must be active to keep the SPI uploads stored on the chip. The SPI clock speed must be slower by a factor of 30 when compared to the system clock (315 MHz nominal speed).

Figure 10. Write Access (C = '1')



The 'out' line is held to High Z. The data for the address A is transferred from the shift register to the active register bank (that is, sampled) on a rising edge of cs_n. Only the

register block with address A can write its data on the 'out' bus. The data on 'in' is ignored.

Figure 11. Read Access (C = '0')

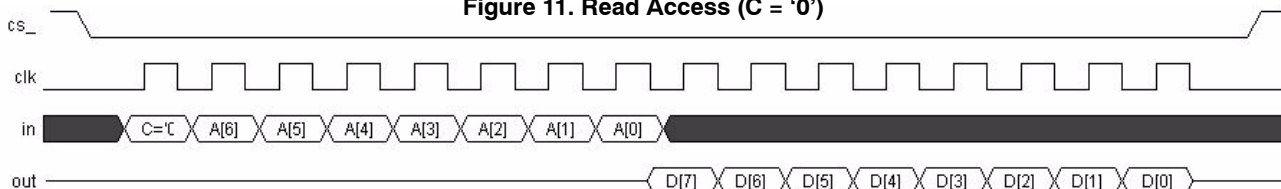


IMAGE SENSOR TIMING AND READOUT

Frame Rate and Windowing

Frame Rate

The frame rate depends on the input clock, the frame overhead time (FOT), and the row overhead time (ROT). The frame period is calculated as follows:

$$1 \text{ kernel} = 24 \text{ Pixels} = 2 \text{ Timeslots} = 2 \text{ Granularity clock cycles}$$

Table 10. FRAME RATE PARAMETERS

| Parameter | Comment | Clarification |
|--------------|-------------------------------------|---|
| FOT | Frame Overhead Time | Programmable: Default 315 granularity clock cycles (5 μ s at 63 MHz) |
| ROT | Row Overhead Time | Programmable: Default 9 granularity clock cycles (143.1 ns at 63 MHz) |
| Nr. Lines | Number of lines read out each frame | Number of lines in ROI |
| Nr. Pixels | Number of pixels read out each line | Number of pixels in ROI |
| Clock Period | 1/63 MHz = 15.9 ns | Every channel works at 63 MHz \rightarrow 12 channels result in 756 MHz data rate |

NOTE: For more information on FPS calculation, refer the ON Semiconductor application note AN57864.

In global shutter mode, the whole pixel array is integrated simultaneously including the dummy line for FPN correction.

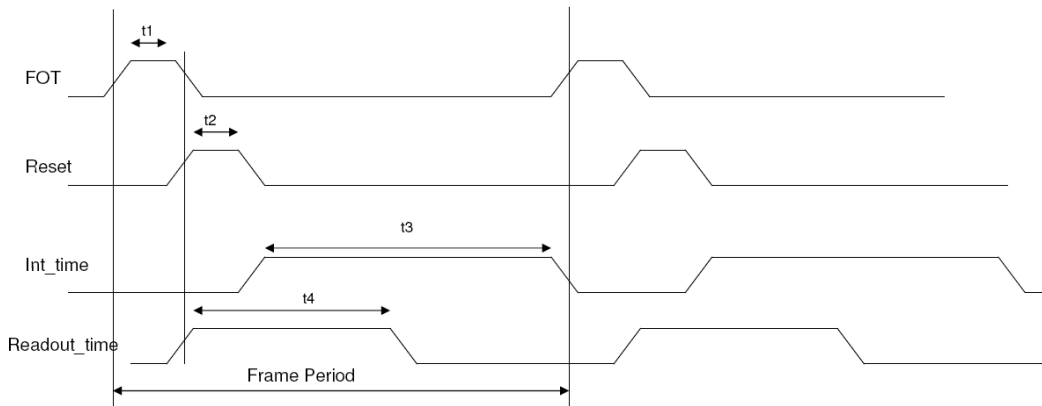


Figure 12. Timing Diagram

Windowing

Windowing is easily achieved by SPI. The starting point of the x and y address and the window size can be uploaded. The minimum step size in the x-direction is 24 pixels (choose only multiples of 24 as start or stop addresses). The minimum step size in the y-direction is one line (every line can be addressed) in normal mode, and two lines in sub sampling mode.

The section Sequencer and Logic on page 11 discusses the use of registers to achieve the desired ROI.

Table 11. TYPICAL FRAME RATES AT 315 MHz

| Image Resolution (X*Y) | Frame Read Out Time (ms) | Frame Rate (fps) |
|------------------------|--------------------------|------------------|
| 1296 x 1024 | 1.9760 | 506 |
| 1008 x 1000 | 1.5807 | 633 |
| 816 x 600 | 0.7997 | 1250 |
| 648 x 480 | 0.5370 | 1862 |
| 528 x 512 | 0.4887 | 2046 |
| 264 x 256 | 0.1596 | 6266 |
| 144 x 128 | 0.0640 | 15625 |
| 24 x 2 | 0.0098 | 102249 |

Operation and Signaling

Digital Signals

Depending on the operation mode (Master or Slave), the pixel array of the image sensor requires different digital control signals. The function of each signal is listed in this table.

Table 12. OVERVIEW OF DIGITAL SIGNALS

| Signal Name | I/O | Comments |
|-------------|--------|---|
| MONITOR_1 | Output | Output pin for integration timing, high during integration |
| MONITOR_2 | Output | Output pin for dual slope integration timing, high during integration |
| MONITOR_3 | Output | Output pin for triple slope integration timing, high during integration |
| INT_TIME_3 | Input | Integration pin triple slope |
| INT_TIME_2 | Input | Integration pin dual slope |
| INT_TIME_1 | Input | Integration pin first slope |
| RESET_N | Input | Sequencer reset, active LOW |
| CLK | Input | System clock (315 MHz) |
| SPI_CS | Input | SPI chip select |
| SPI_CLK | Input | Clock of the SPI (< Sensor clock/30) |
| SPI_IN | Input | Data line of the SPI, serial input |
| SPI_OUT | Output | Data line of the SPI, serial output |

Global Shutter

In a global shutter, light integration occurs on all pixels in parallel, although subsequent readout is sequential. Figure 12 shows the integration and readout sequence for the global shutter. All pixels are light sensitive at the same period of time. The whole pixel core is reset simultaneously,

and after the integration time, all pixel values are sampled together on the storage node inside each pixel. The pixel core is read out line by line after integration. Note that the integration and readout cycle can occur in parallel (refer to Pipelined Shutter on page 20) or in sequential (refer to Triggered Shutter on page 22) mode.

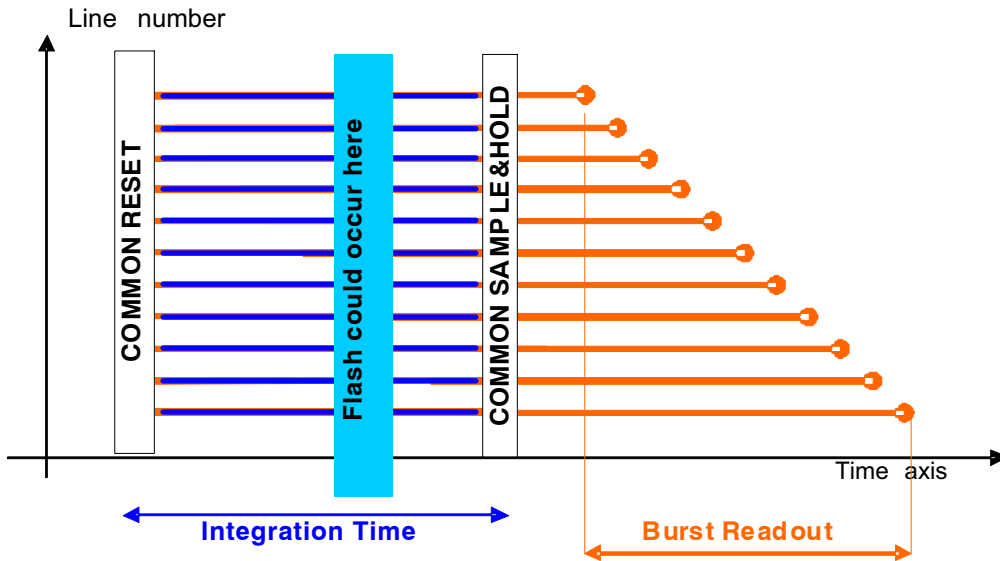


Figure 13. Global Shutter Operation

The timing of the sensor consists of two parts. The first part is related to the exposure time and the control of the pixel. The second part is related to the read out of the image sensor. Integration and readout are in parallel or triggered. In the first case, the integration time of frame I is ongoing during the readout of frame I-1. Figure 13 shows this parallel timing structure.

The readout of every frame starts with a FOT, during which the analog value on the pixel diode is transferred to the pixel memory element. After this FOT, the sensor is read out line by line. The read out of every line starts with a ROT, during which the pixel value is put on the column lines. Then

the pixels are selected in groups of 24 (12 on rising edge, and 12 on the falling edge of the internal clock). So in total, 54 kernels of 24 pixels are read out every line. The internal timing is generated by the sequencer. The sequencer can operate in two modes: master mode and slave mode. In master mode, all internal timing is controlled by the sequencer, based on the SPI settings. In slave mode, the integration timing is directly controlled by over three pins, and the readout timing is still controlled by the sequencer. The seqmode1[1] register of the SPI selects between the master and slave modes.

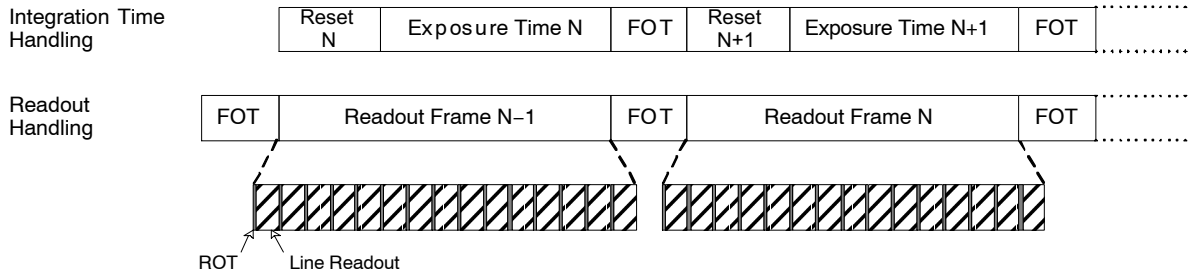


Figure 14. Global Readout Timing (Parallel)

Pipelined Shutter

Integration and readout occur in parallel and are continuous. You only need to start and stop the batch of image captures.

Integration of frame N is always ongoing during readout of frame N-1. The readout of every frame starts with a FOT, during which the analog value on the pixel diode is transferred to the pixel memory element. After this FOT, the sensor is read out line by line. The readout of every line starts

with a ROT, during which the pixel value is put on the column lines. Then the pixels are mixed in the correct ADCs, processed, and then sent to the LVDS output block.

You have two options in the pipelined shutter mode. The first option is to program the reset and integration through the configuration interface and let the sequencer handle integration time automatically. This mode is called master mode. The second option is to drive the integration time through an external pin. This mode is called slave mode.

Programming the Exposure Time

In master mode, the exposure time is configured in two distinct methods (controlled by register seqmode3[6]):

- # lines: Obvious, changing signals that control integration time. They are always changed during ROT to avoid any image artefacts.
- # clock cycles: Must be multiplied by (2*seqmode4[3:0]). When the counter expires, changes are put into effect immediately. Asserting the configuration signal (seqmode3[7]) forces delaying signal updates until the next ROT.

Table 13 lists the user programmable timer settings and how they are interpreted by the hardware.

Table 13. USER PROGRAMMABLE TIMER SETTINGS

| Setting | Granularity |
|-----------------------|--------------|
| reg_res_length | Lines/cycles |
| reg_tint_timer | Lines/cycles |
| reg_tint_ds_timer | Lines/cycles |
| reg_tint_ts_timer | Lines/cycles |
| res_dsts_length | Lines/cycles |
| reg_rot_timer | clock cycles |
| reg_fot_timer | clock cycles |
| reg_sel_pre_timer | clock cycles |
| reg_precharge_timer | clock cycles |
| reg_sample_timer | clock cycles |
| reg_vmem_timer | clock cycles |
| reg_delayed_rdt_timer | Lines/cycles |

Note that the seqmode3[7] can also be used to sync the user signals in slave mode. The behavior is exactly the same.

Master Mode

In master mode the reset and exposure time is written in registers.

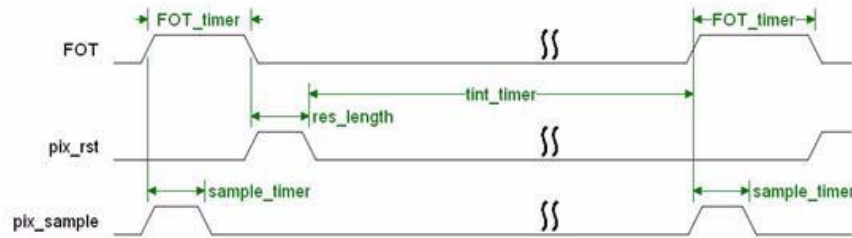


Figure 15. Integration and Image Readout in Master Mode

Ensure that the added value of the registers res_length and tint_timer always exceeds the number of lines that are read out. This is because the sequencer samples a new image after

integration is complete, without checking if image readout is finished. Enlarging res_length to accommodate for this has no impact on image capture.

Slave Mode

In slave mode, the register values of `res_length` and `tint_timer` are ignored. The integration time is controlled by the `int_time` pin. The relationship between the input pin and the integration time is shown in Figure 15. When the input

`int_time` is asserted, the pixel array goes out of reset and exposure can begin. When `int_time` goes low again and the desired exposure time is reached, the image is sampled and read out can begin.

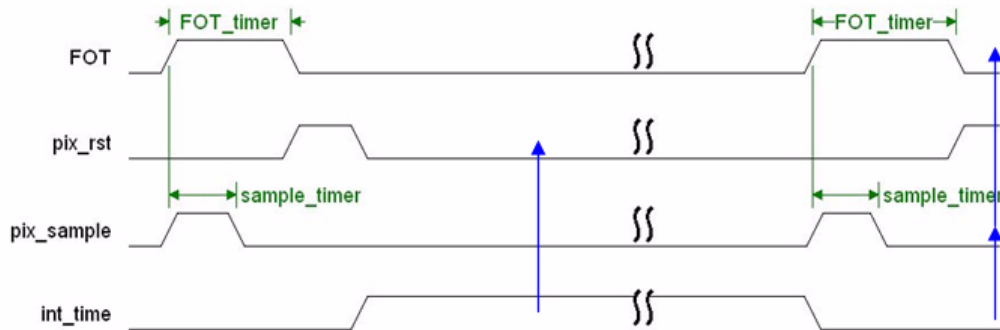


Figure 16. Integration and Image Readout in Slave Mode

Changing pixel's reset level during line readout might result in image artefacts during a small transient period. As

a result, it is advised to only change the value of `int_time` during ROT.

Triggered Shutter

The two main differences in the pipelined shutter mode are:

- One single image is read upon every user action.
- Integration (and read out) is under control of the user through pin `int_time`.

This means that for every frame, you need to manually intervene. The pixel array is kept in reset state until you assert the `int_time` input. Similar to the pipelined shutter mode, there is a master mode in which the sequencer can control the integration time, or a slave mode in which you can define the integration time.

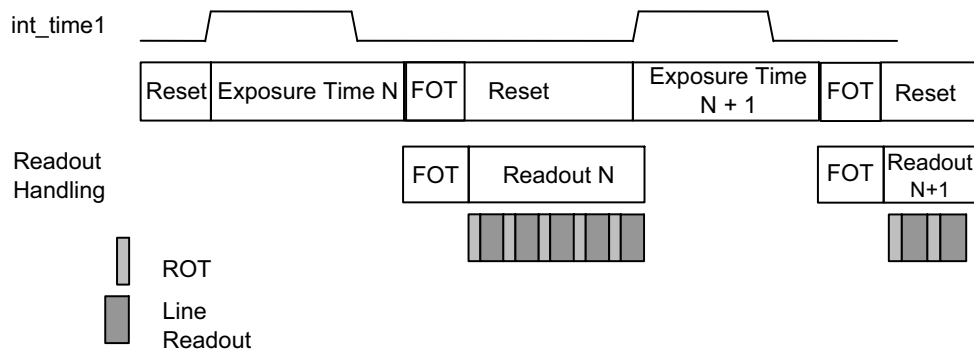


Figure 17. Integration and Readout for Triggered Shutter

The possible applications for this triggered shutter mode are:

- Synchronize external flash with exposure
- Apply extremely long integration times (only in slave mode)

Master Mode

In this mode, a rising edge on int_time1 pin is used to trigger the start of integration and read out. The tint_timer defines the integration time independent of the assertion of the input pin int_time1. After the integration time counter runs out, the FOT automatically starts and the image readout is done. During readout, the image array is kept in reset. A request for a new frame is started again when a new rising edge on int_time is detected. The time of the falling edge is not important in this mode.

Slave Mode

Integration time control is identical to the pipelined shutter slave mode. The int_time1 pin controls the start of integration. When int_time is deasserted, the FOT starts (analog value on the pixel diode is transferred to the pixel memory element). Only at that time, image read out can start (similar to the pipelined read out). During read out, the image array is kept in reset. A request for a new frame is started when int_time goes high again.

Non Destructive Readout (NDR)

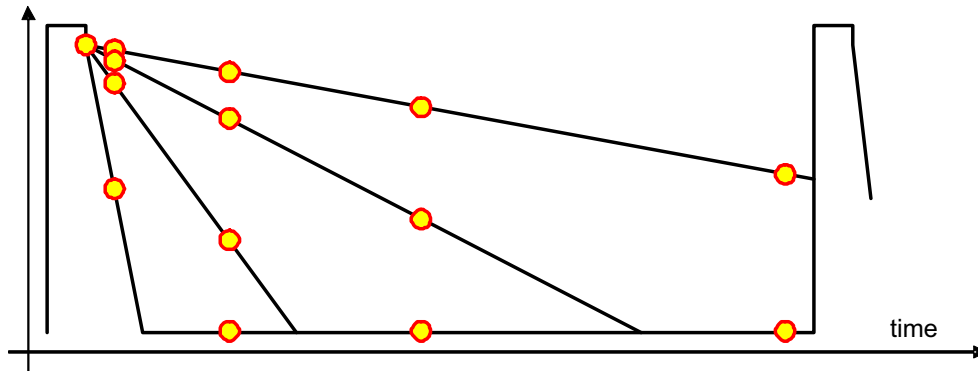


Figure 18. Principle of Non Destructive Readout

The sensor can also be read out in a nondestructive method. After a pixel is initially reset, it can be read multiple times, without being reset. You can record the initial reset level and all intermediate signals. High light levels saturate the pixels quickly, but a useful signal is obtained from the early samples. For low light levels, the later or latest samples

must be used. Essentially, an active pixel array is read multiple times, and reset only once. The external system intelligence interprets the data. Table 14 on page 23 summarizes the advantages and disadvantages of nondestructive readout.

Table 14. ADVANTAGES AND DISADVANTAGES OF NON DESTRUCTIVE READOUT

| Advantages | Disadvantages |
|---|---|
| Low noise, because it is true CDS | System memory required to record the reset level and the intermediate samples |
| High sensitivity. The conversion capacitance is kept low. | Requires multiples readings of each pixel, so there is higher data throughput |
| High dynamic range. The results include signals for short and long integration times. | Requires system level digital calculations |

Note that the amount of samples taken with one initial reset is programmable in the nr_of_ndr_steps register. If nr_of_ndr_steps is one, the sensor operates in the default method, that is one reset and one sample. This is called the disable nondestructive read out mode.

When nr_of_ndr_steps is two, there is one reset and two samples, and so on. In the slave mode, nothing changes on the protocol of the signals int_time*. The sequencer suppresses the internal reset signal to the pixel array.

Image Format and Read Out Protocol

The active area read out by the sequencer in full frame mode is shown in Figure 18. Before the actual pixels are read out, one dummy line is read to enable column FPN correction. A reference voltage is applied to the columns and the entire line is read as if real pixel values are placed on the columns.

Pixels are always read in multiples of 24 (one value to every channel in the AFE). The last time slot contains not only valid pixels, but also two dummy columns, six grey columns, and eight black columns.

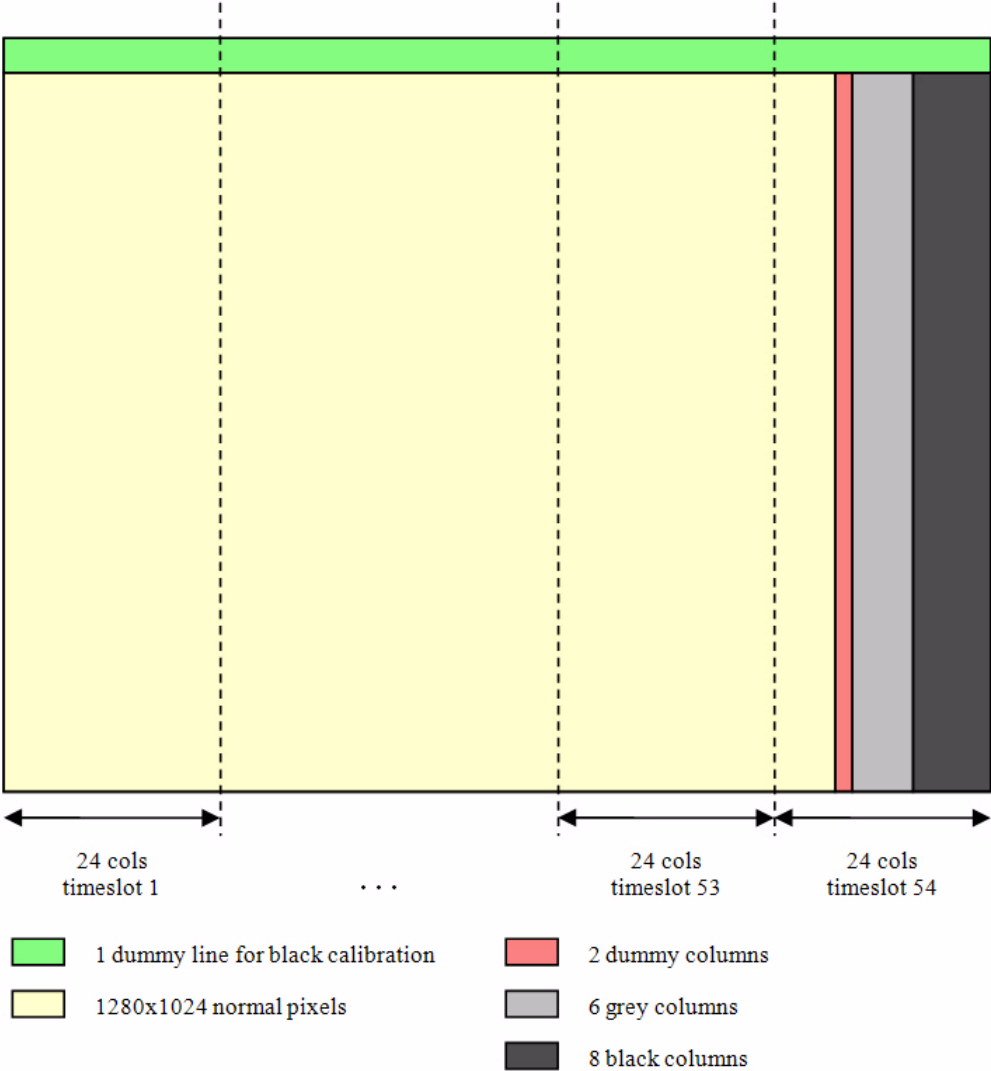


Figure 19. Sensor Read Out Format

NOIL2SM1300A

The following sections discuss the appearance of the output (data and synchronization codes) in several relevant configurations. Twelve output channels are connected to the 24 ADCs and handle the data. One additional channel contains all the synchronization codes for the receiver. This indicates, for example, the start of a frame, the end of a frame, whether the data channels contain data, CRC, a training pattern, and so on. The sequencer provides the synchronization channel with the correct synchronization or protocol signals, as shown in Figure 7. The synchronization codes are listed in Table 15. Note that a FS also serves as LS, and vice versa.

Table 15. SYNCHRONIZATION CODES

| Sync code | Abbreviation | 10-Bit Code |
|-------------------|--------------|-------------|
| Frame Start | FS | 0x059 |
| Line Start | LS | 0x056 |
| Frame End | FE | 0x05A |
| Line End | LE | 0x055 |
| Grey/Black Cols | GBC | 0x0A9 |
| CRC | CRC | 0x0A6 |
| FPN stored values | FPN | 0x13C |
| Normal Data | D | 0x193 |
| Training Pattern | T | T |

This table provides a detailed overview of remapping one full row read out.

Table 16. REMAPPING SCHEME FOR ONE ROW

| timeslot | ch0 | ch1 | ch2 | ch3 | ch4 | ch5 | ch6 | ch7 | ch8 | ch9 | ch10 | ch11 |
|----------|------|------|------|------|------|------|------|------|------|------|------|------|
| 1a | 0 | 2 | 4 | 6 | 8 | 10 | 12 | 14 | 16 | 18 | 20 | 22 |
| 1b | 1 | 3 | 5 | 7 | 9 | 11 | 13 | 15 | 17 | 19 | 21 | 23 |
| 2a | 47 | 45 | 43 | 41 | 39 | 37 | 35 | 33 | 31 | 29 | 27 | 25 |
| 2b | 46 | 44 | 42 | 40 | 38 | 36 | 34 | 32 | 30 | 28 | 26 | 24 |
| 3a | 48 | 50 | 52 | 54 | 56 | 58 | 60 | 62 | 64 | 66 | 68 | 70 |
| 3b | 49 | 51 | 53 | 55 | 57 | 59 | 61 | 63 | 65 | 67 | 69 | 71 |
| 4a | 95 | 93 | 91 | 89 | 87 | 85 | 83 | 81 | 79 | 77 | 75 | 73 |
| 4b | 94 | 92 | 90 | 88 | 86 | 84 | 82 | 80 | 78 | 76 | 74 | 72 |
| 5a | 96 | 98 | 100 | 102 | 104 | 106 | 108 | 110 | 112 | 114 | 116 | 118 |
| 5b | 97 | 99 | 101 | 103 | 105 | 107 | 109 | 111 | 113 | 115 | 117 | 119 |
| 6a | 143 | 141 | 139 | 137 | 135 | 133 | 131 | 129 | 127 | 125 | 123 | 121 |
| 6b | 142 | 140 | 138 | 136 | 134 | 132 | 130 | 128 | 126 | 124 | 122 | 120 |
| 7a | 144 | 146 | 148 | 150 | 152 | 154 | 156 | 158 | 160 | 162 | 164 | 166 |
| 7b | 145 | 147 | 149 | 151 | 153 | 155 | 157 | 159 | 161 | 163 | 165 | 167 |
| 8a | 191 | 189 | 187 | 185 | 183 | 181 | 179 | 177 | 175 | 173 | 171 | 169 |
| 8b | 190 | 188 | 186 | 184 | 182 | 180 | 178 | 176 | 174 | 172 | 170 | 168 |
| 9a | 192 | 194 | 196 | 198 | 200 | 202 | 204 | 206 | 208 | 210 | 212 | 214 |
| 9b | 193 | 195 | 197 | 199 | 201 | 203 | 205 | 207 | 209 | 211 | 213 | 215 |
| 10a | 239 | 237 | 235 | 233 | 231 | 229 | 227 | 225 | 223 | 221 | 219 | 217 |
| 10b | 238 | 236 | 234 | 232 | 230 | 228 | 226 | 224 | 222 | 220 | 218 | 216 |
| 11a | 240 | 242 | 244 | 246 | 248 | 250 | 252 | 254 | 256 | 258 | 260 | 262 |
| 11b | 241 | 243 | 245 | 247 | 249 | 251 | 253 | 255 | 257 | 259 | 261 | 263 |
| 12a | 287 | 285 | 283 | 281 | 279 | 277 | 275 | 273 | 271 | 269 | 267 | 265 |
| 12b | 286 | 284 | 282 | 280 | 278 | 276 | 274 | 272 | 270 | 268 | 266 | 264 |
| ... | ... | ... | ... | ... | ... | ... | ... | ... | ... | ... | ... | ... |
| ... | ... | ... | ... | ... | ... | ... | ... | ... | ... | ... | ... | ... |
| 53a | 1248 | 1250 | 1252 | 1254 | 1256 | 1258 | 1260 | 1262 | 1264 | 1266 | 1268 | 1270 |
| 53b | 1249 | 1251 | 1253 | 1255 | 1257 | 1259 | 1261 | 1263 | 1265 | 1267 | 1269 | 1271 |
| 54a | 1295 | 1293 | 1291 | 1289 | 1287 | 1285 | 1283 | 1281 | 1279 | 1277 | 1275 | 1273 |

NOIL2SM1300A

Table 16. REMAPPING SCHEME FOR ONE ROW

| timeslot | ch0 | ch1 | ch2 | ch3 | ch4 | ch5 | ch6 | ch7 | ch8 | ch9 | ch10 | ch11 |
|----------|------|------|------|------|------|------|------|------|------|------|------|------|
| 54b | 1294 | 1292 | 1290 | 1288 | 1286 | 1284 | 1282 | 1280 | 1278 | 1276 | 1274 | 1272 |
| CRC | | | | | | | | | | | | |

Table 17. REMAPPING SCHEME FOR ONE ROW IN REVERSE X/Y READOUT MODE

| Timeslot | ch0 | ch1 | ch2 | ch3 | ch4 | ch5 | ch6 | ch7 | ch8 | ch9 | ch10 | ch11 |
|----------|------|------|------|------|------|------|------|------|------|------|------|------|
| 54a | 1295 | 1293 | 1291 | 1289 | 1287 | 1285 | 1283 | 1281 | 1279 | 1277 | 1275 | 1273 |
| 54b | 1294 | 1292 | 1290 | 1288 | 1286 | 1284 | 1282 | 1280 | 1278 | 1276 | 1274 | 1272 |
| 53a | 1248 | 1250 | 1252 | 1254 | 1256 | 1258 | 1260 | 1262 | 1264 | 1266 | 1268 | 1270 |
| 53b | 1249 | 1251 | 1253 | 1255 | 1257 | 1259 | 1261 | 1263 | 1265 | 1267 | 1269 | 1271 |
| ... | ... | ... | ... | ... | ... | ... | ... | ... | ... | ... | ... | ... |
| ... | ... | ... | ... | ... | ... | ... | ... | ... | ... | ... | ... | ... |
| 2a | 47 | 45 | 43 | 41 | 39 | 37 | 35 | 33 | 31 | 29 | 27 | 25 |
| 2b | 46 | 44 | 42 | 40 | 38 | 36 | 34 | 32 | 30 | 28 | 26 | 24 |
| 1a | 0 | 2 | 4 | 6 | 8 | 10 | 12 | 14 | 16 | 18 | 20 | 22 |
| 1b | 1 | 3 | 5 | 7 | 9 | 11 | 13 | 15 | 17 | 19 | 21 | 23 |
| CRC | | | | | | | | | | | | |

Table 18. REMAPPING SCHEME FOR ONE ROW IN COLOR SUBSAMPLING MODE

| Timeslot | ch0 | ch1 | ch2 | ch3 | ch4 | ch5 | ch6 | ch7 | ch8 | ch9 | ch10 | ch11 |
|----------|------|------|------|------|------|------|------|------|------|------|------|------|
| 1a | 0 | 45 | 4 | 41 | 8 | 37 | 12 | 33 | 16 | 29 | 20 | 25 |
| 1b | 1 | 44 | 5 | 40 | 9 | 36 | 13 | 32 | 17 | 28 | 21 | 24 |
| 2a | 48 | 93 | 52 | 89 | 56 | 85 | 60 | 81 | 64 | 77 | 68 | 73 |
| 2b | 49 | 92 | 53 | 88 | 57 | 84 | 61 | 80 | 65 | 76 | 69 | 72 |
| ... | ... | ... | ... | ... | ... | ... | ... | ... | ... | ... | ... | ... |
| ... | ... | ... | ... | ... | ... | ... | ... | ... | ... | ... | ... | ... |
| 27a | 1248 | 1293 | 1252 | 1289 | 1256 | 1285 | 1260 | 1281 | 1264 | 1277 | 1268 | 1273 |
| 27b | 1249 | 1292 | 1253 | 1288 | 1257 | 1284 | 1261 | 1280 | 1265 | 1276 | 1269 | 1272 |
| CRC | | | | | | | | | | | | |

Table 19. REMAPPING SCHEME FOR ONE ROW IN MONOCHROME SUBSAMPLING MODE

| Timeslot | ch0 | ch1 | ch2 | ch3 | ch4 | ch5 | ch6 | ch7 | ch8 | ch9 | ch10 | ch11 |
|----------|------|------|------|------|------|------|------|------|------|------|------|------|
| 1a | 0 | 2 | 4 | 6 | 8 | 10 | 12 | 14 | 16 | 18 | 20 | 22 |
| 1b | 46 | 44 | 42 | 40 | 38 | 36 | 34 | 32 | 30 | 28 | 26 | 24 |
| 2a | 48 | 50 | 52 | 54 | 56 | 58 | 60 | 62 | 64 | 66 | 68 | 70 |
| 2b | 94 | 92 | 90 | 88 | 86 | 84 | 82 | 80 | 78 | 76 | 74 | 72 |
| 3a | 96 | 98 | 100 | 102 | 104 | 106 | 108 | 110 | 112 | 114 | 116 | 118 |
| 3b | 142 | 140 | 138 | 136 | 134 | 132 | 130 | 128 | 126 | 124 | 122 | 120 |
| 4a | 144 | 146 | 148 | 150 | 152 | 154 | 156 | 158 | 160 | 162 | 164 | 166 |
| ... | ... | ... | ... | ... | ... | ... | ... | ... | ... | ... | ... | ... |
| ... | ... | ... | ... | ... | ... | ... | ... | ... | ... | ... | ... | ... |
| 27a | 1248 | 1250 | 1252 | 1254 | 1256 | 1258 | 1260 | 1262 | 1264 | 1266 | 1268 | 1270 |
| 27b | 1294 | 1292 | 1290 | 1288 | 1286 | 1284 | 1282 | 1280 | 1278 | 1276 | 1274 | 1272 |
| CRC | | | | | | | | | | | | |

NOIL2SM1300A

Single Window Mode Not Containing Timeslot 54

In this operation mode, only part of the sensor is read out, as shown in Figure 21. Although the window is defined as

not containing any data from timeslot 54, it is read out to provide information on grey and black columns to the user.

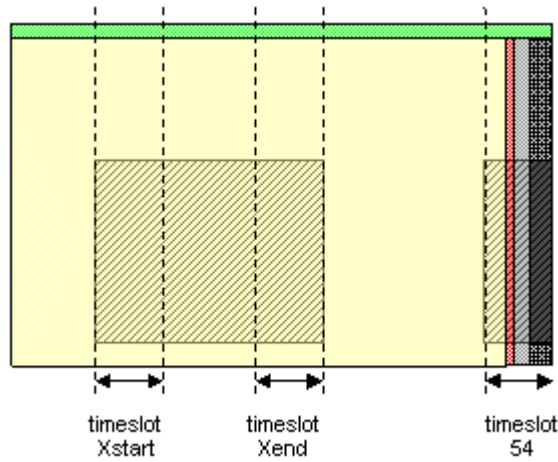


Figure 22. Single Window Not Containing Timeslot 54

Figure 22 shows the internal state of the sequencer, and the behavior of the data and sync channels (overview and detail of one line) for this window mode.

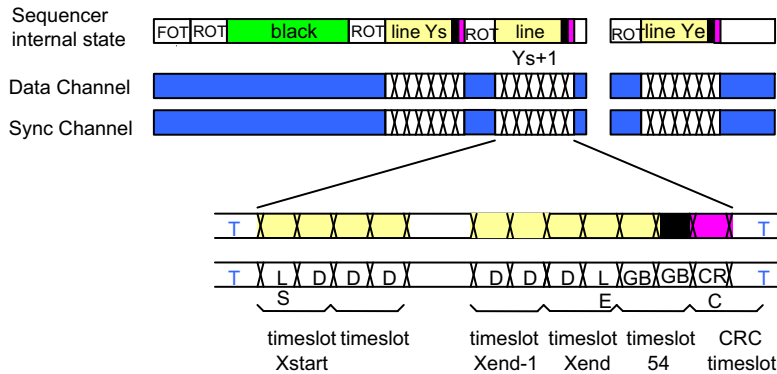


Figure 23. Waveform for Single Window NOT Containing Timeslot 54

Note that the dummy black line is read completely.

Reading out multiple windows does not differ from combining the windowed modes in sections Single Window Mode Containing Timeslot 54 on page 27 and Single Window Mode Not Containing Timeslot 54. The dummy

black line again spans the entire width of the sensor and is processed only once, before all configured windows are read. The dummy black line is independent of the window sizes.

ADDITIONAL FEATURES

Windowing

A fully configurable window can be selected for readout.

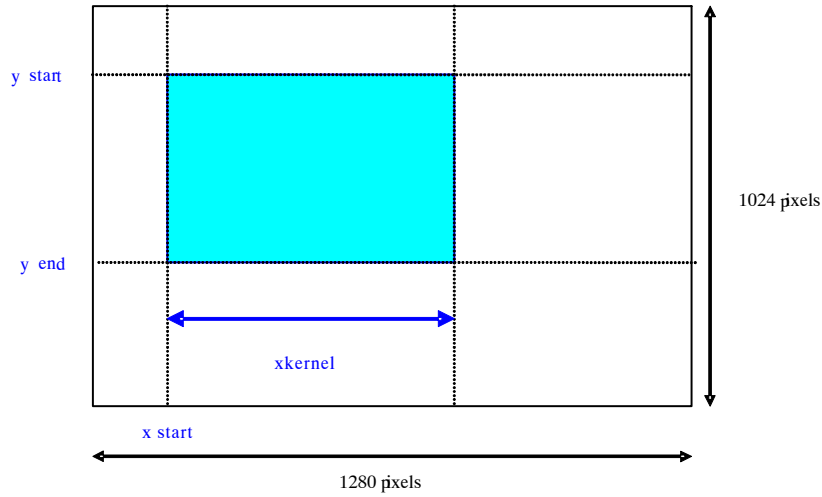


Figure 24. Window Selected for Readout

The parameters to configure this window are:

x_start. The sensor reads out 24 pixels in one single clock cycle. The granularity of configuring the X start position is also 24. Every value written to the windowX_2 register must be multiplied by 24 to find the corresponding column in the pixel array.

x_kernels. The number of columns that is read out ($x_kernels * 24$ in full frame mode) in subsampling mode $x_kernels * 48$ represents the number of columns over which subsampling is done. The $x_kernels$ value must be written to the windowX_4 register.

y_start. The starting line of the readout window, granularity of 1. Note that in subsample mode, the correct y_start position must be uploaded (exact value depends on color or B/W subsampling mode). This value must be written to the windowX_1 and windowx_2 register.

y_end. The end line of the readout window, granularity of 1. In all cases (even in reverse scan), y_end are larger than y_start . Note that in subsample mode, the correct y_end position must be uploaded (exact value depends on color or B/W subsampling mode). This value must be written to the windowX_3 and windowX_4 register.

In case of windowing, the effective readout time is smaller than in full frame mode, because only the relevant part of the image array is accessed. As a result, it is possible to achieve higher frame rates.

Subsampling

Subsampling reduces resolution while maintaining the constant field of view and an increased frame rate. LUPA1300-2 supports monochrome and color subsampling modes of operation. The pixel order for one complete row is shown in Table 18 and Table 19 on page 26.

Reverse Scan

Reverse scanning is supported in the X and Y direction. Line 0 (first line on the output) is the top line in normal mode and the bottom line in reverse scanning, as shown in Figure 24. As a result, the line numbers always increment.

When reverse scanning in X, the operation is analogous. To enable reverse readout in X and Y, set the seqmode4[6:7] bits. In addition, the Y_start and X_start addresses must be changed to the new starting address.

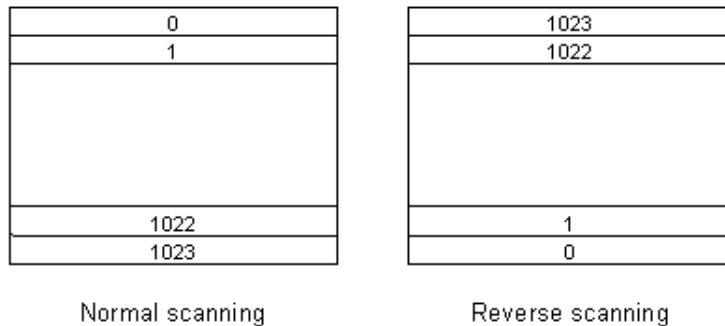


Figure 25. Normal and Reverse Scanning in Y

Multiple Windows

The sequencer supports the readout of four different windows, randomly positioned over the pixel array. The images are read out sequentially. That is, window 1 is read out before window 2, even if both windows show some overlap. Next, windows 3 and 4 are read out. Each window is treated as a frame and images are read out as shown in Figure 26. Also, the sum of readout times of all four

windows should be less than or equal to the sum of reset time and integration time. $(RTw1+RTw2+RTw3+RTw4) < (Reset\ time + Integration\ time)$. You can configure the number of windows used in the application (one to four). Figure 25 shows how to configure two windows spread over the image array.

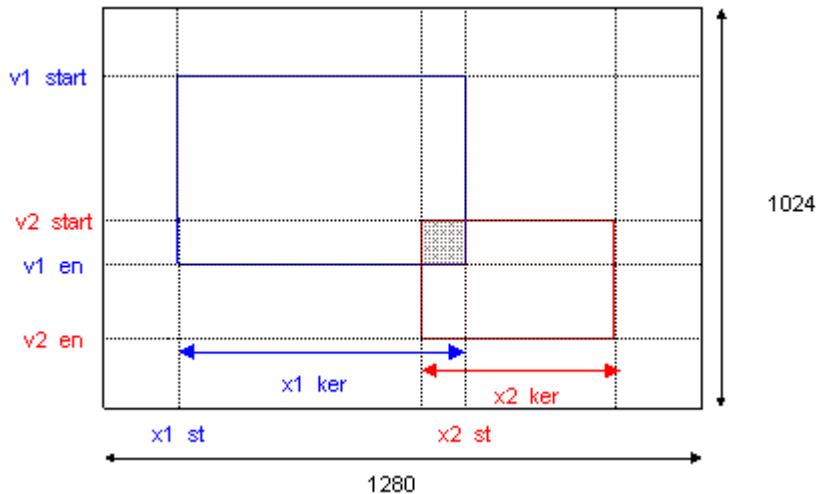


Figure 26. Multiple Windows Read from the Same Pixel Array

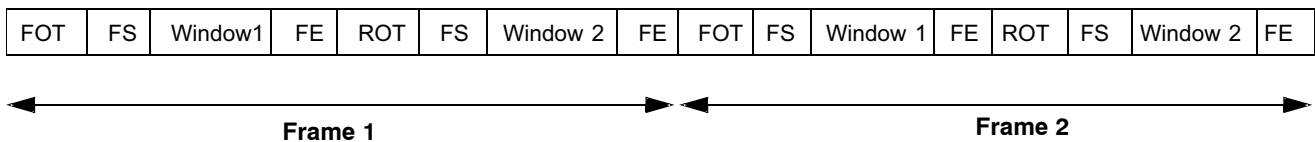


Figure 27. Readout from Windows

Figure 27 shows the sequence of integration and read out for multiple windows. The handling of integration time is identical to the single window mode (except that in this case, the maximum integration time is equal to the sum of the

y_widths of the two windows). Read out starts with a FOT that is similar to single window mode. After the FOT, all lines of window 1 are read, followed by the lines of window 2.

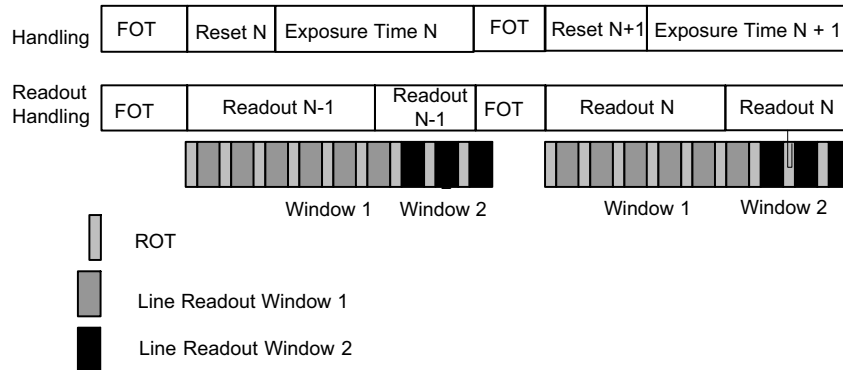


Figure 28. Exposure and Read Out of Multiple Windows

If the X size of the windows are not identical, the integration time in function of the number of lines read presents multiple slopes (proportional to the X size of these windows). Because this can cause confusion when programming the integration time, it is easier to configure all timer registers using the clock cycle configuration instead of the 'line' configuration.

Multiple Slopes

Dynamic range can be extended by the multiple slope capabilities of the sensor. The four colored lines in Figure 28 represent analog signals of the photodiode of four pixels, which decrease as a result of exposure. The slope is determined by the amount of light at each pixel (the more light, the steeper the slope). When the pixels reach the saturation level, the analog does not change despite further

exposure. Without the multiple slope capabilities, the pixels p3 and p4 are saturated before the end of the exposure time, and no signal is received. However, when using multiple slopes, the analog signal is reset to a second or third reset level (lower than the original) before the integration time ends. The analog signal starts decreasing with the same slope as before, and pixels that were saturated before could be nonsaturated at read out time. For pixels that never reach any of the reset levels (for example, p1 and p2) there is no difference between single and multiple slope operation.

By choosing the time stamps of the double and triple slope resets (typical at 90% and 99% of the integration, configurable by the user), it is possible to have a nonsaturated pixel value even for pixels that receive a huge amount of light.

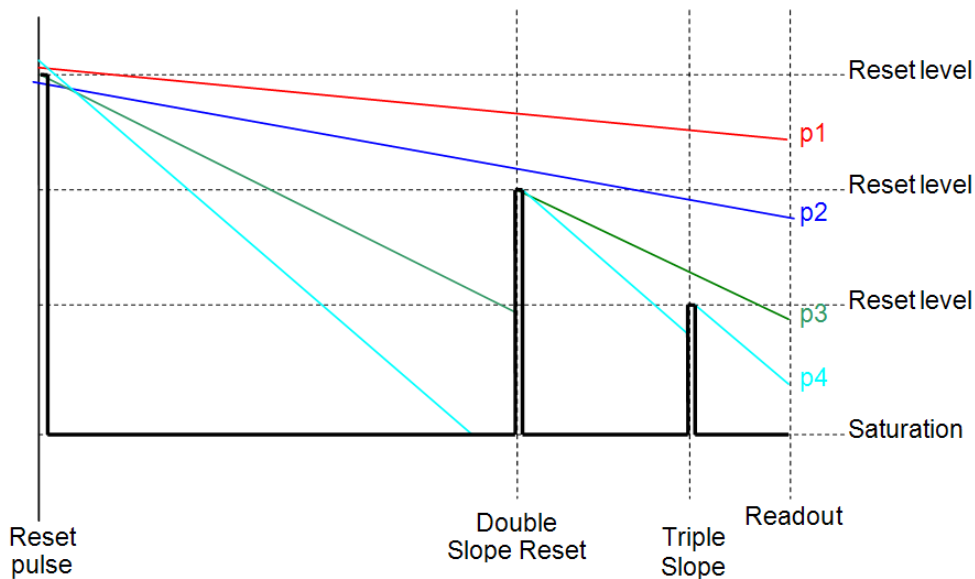


Figure 29. Dynamic Range Extended by Multiple Slope Capability

NOIL2SM1300A

The reset levels are configured through external (power) pins. In master mode, the time stamps of the double and triple slope resets are configured in a method similar to configuring the exposure time. The time stamps are enabled

through the registers seqmode1[5] and seqmode1[6], and their values are expressed in line or clock cycles in the registers reg_tint_ds_timer and reg_tint_ts_timer.

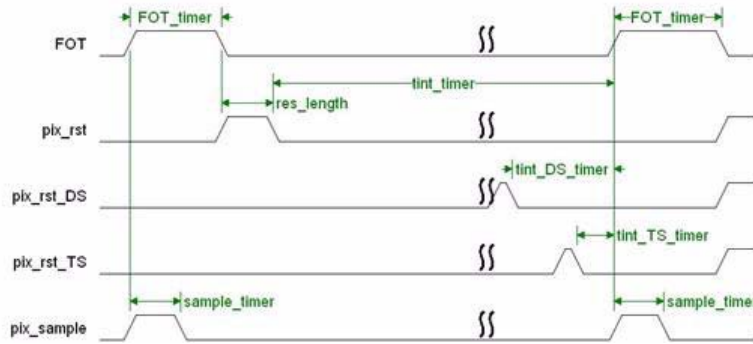


Figure 30. Triple Slope Timing in Master Mode

In slave mode, the values of res_length, tint_timer, tint_DS_timer, and tint_TS_timer in the configuration registers are ignored. You have full control through the pins

int_time, int_time_ds, and int_time_ts. You must configure the multiple slope parameters for the application and interpret the pixel data accordingly.

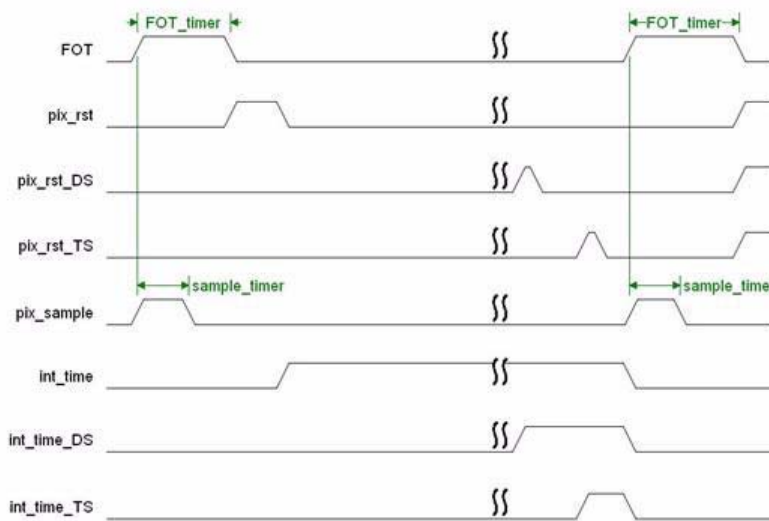


Figure 31. Triple Slope Timing in Slave Mode

Column FPN Correction

The column FPN of the sensor is improved by the offset correction of the columns. At the start of every frame, before read out of the actual lines is done, a fixed voltage is applied at the columns and these values are read out like a real data line. Inside the data block, the 'pixel' data for that line is stored in an on-chip FPN memory. When the correction is enabled, the corresponding FPN value is subtracted from the incoming pixel data.

This FPN correction must be enabled for every output separately. The registers used to configure the correction are:

- **datachannelX_1 with X from 0 to 11.** The field [1] of these registers enables the offset corrections of the specific output channel.

NOTE: Do not change the settings of datachannel12_1. This channel contains synchronization data, not pixel data. If fpn correction is enabled on this channel, the synchronization data becomes corrupt.

- **seqmode3.** The field[2] must be '1'. It enables the generation of the line of reference voltages at the columns.

Figure 31 and Figure 32 show the effect of enabling the column FPN correction. These images are magnified up to five times.

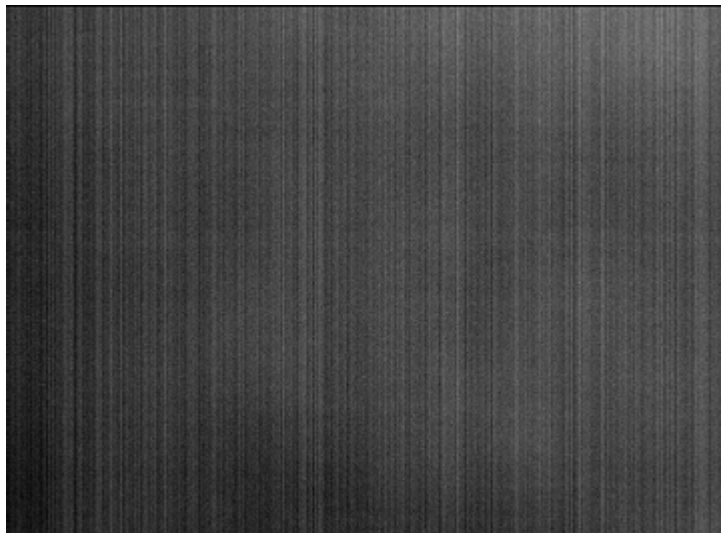


Figure 32. Dark Image Without FPN Correction (5x Amplified)

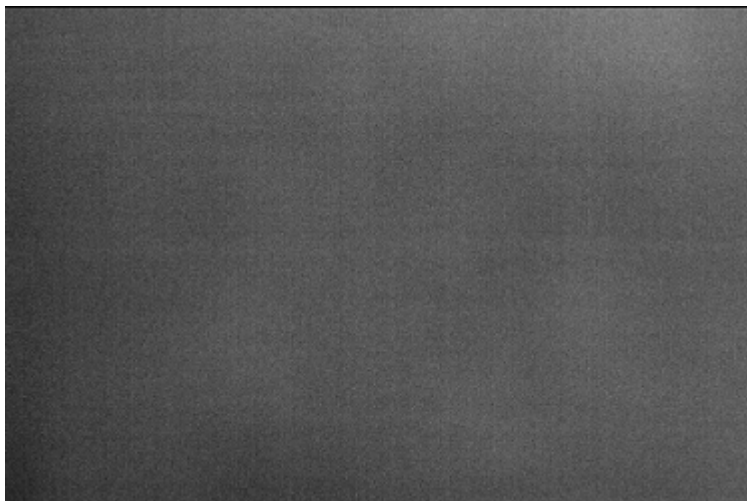


Figure 33. Dark Image With FPN Correction Enabled (5x Amplified)

Full Frame Mode

In this operation mode, the entire sensor shown in Figure 18 on page 24 is read out. Figure 33 shows the

internal state of the sequencer, and the behavior of the data and sync channels (overview and detail of one line).

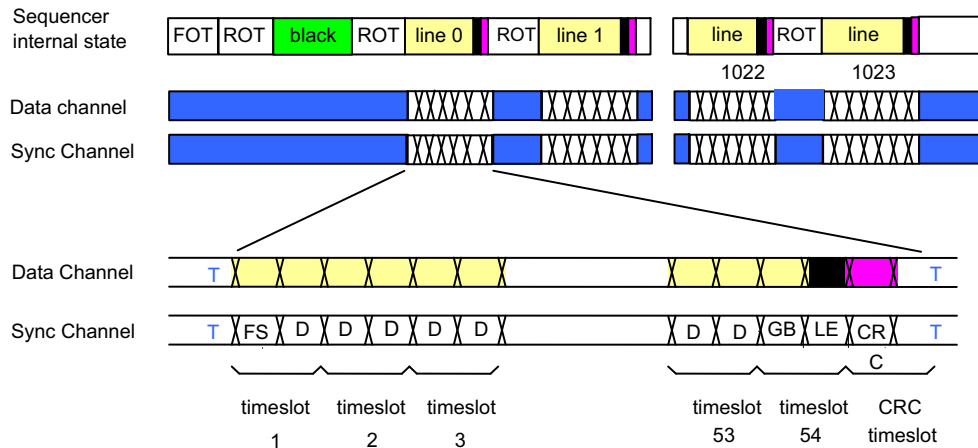


Figure 34. Full Frame Mode Readout

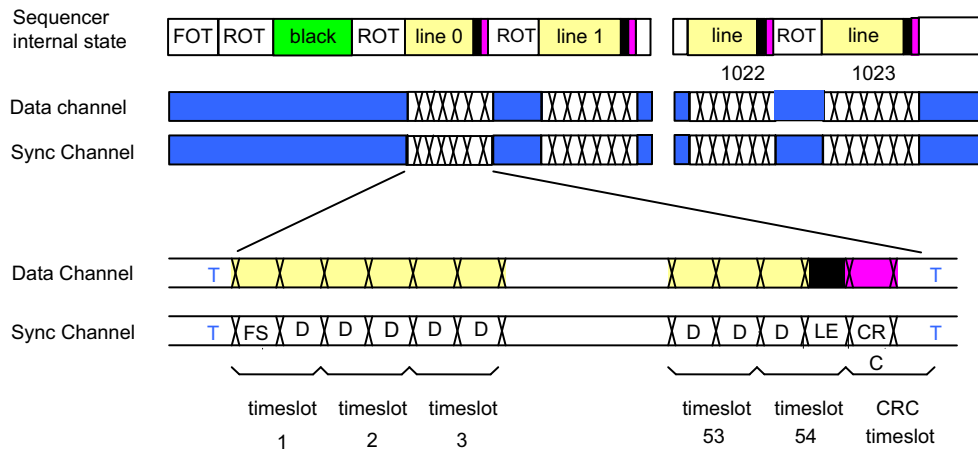


Figure 35. Full Frame Mode Readout with On Chip Black Level Calibration Disabled

Off Chip Automatic Black Level Calibration

The last time slot not only contains valid pixels but also two dummy columns, six grey columns, and eight black columns. The grey column values are used to perform off chip black level calibration to maintain a constant black level against any type of drift. These values gauge the response of normal pixels in the dark conditions.

Grey columns are generated by applying a minimal integration time (black timer register) to the columns. Black columns share the same minimal integration time; additionally, the pixels in that column are shielded. Grey columns can be used if the integration time is large compared to the minimal integration time. Black columns are used if the integration time is in the same order of magnitude as the minimal integration time.

The procedure is as follows:

1. Decide what digital code should be the desired black level. 0x00 cannot be chosen to avoid underflow in FPN correction.

2. Set the sensor to safe settings; DACVREFADC must be on a value that never clips the grey (or black) columns.
 - ♦ Make sure that the grey (or black) columns can be read out without clipping.
 - ♦ Make sure that this is the case for every sensor including dc-shifts due to Vt and temperature differences.
3. Read-out the grey (or black) columns.
4. Calculate the average value of this grey (or black) data; also average it out over the different grey columns.
5. Adapt the DACVREFADC if the calculated value deviate from the desired black level value and return to step (2).
6. Repeat the procedure for temperature changes.

NOIL2SM1300A

PACKAGE

Pin List

Table 20. PIN PLACEMENT LAYOUT (Top View)

| | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 10 | 11 | 12 | 13 | 14 | 15 | 16 | 17 | 18 | 19 | 20 | 21 | 22 | 23 | 24 |
|---|----------|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|----|----|----|----|----|----|----|----|----|----|----|----|
| A | 134 | 130 | 127 | 124 | 121 | 118 | 115 | 112 | 109 | 106 | 103 | 100 | 99 | 96 | 93 | 90 | 87 | 84 | 81 | 78 | 75 | 72 | 69 | 65 |
| B | * | 131 | 128 | 125 | 122 | 119 | 116 | 113 | 110 | 107 | 104 | 101 | 98 | 95 | 92 | 89 | 86 | 83 | 80 | 77 | 74 | 71 | 68 | * |
| C | 133 | 132 | 129 | 126 | 123 | 120 | 117 | 114 | 111 | 108 | 105 | 102 | 97 | 94 | 91 | 88 | 85 | 82 | 79 | 76 | 73 | 70 | 67 | 66 |
| D | TOP VIEW | | | | | | | | | | | | | | | | | | | | | | | |
| E | | | | | | | | | | | | | | | | | | | | | | | | |
| F | | | | | | | | | | | | | | | | | | | | | | | | |
| G | | | | | | | | | | | | | | | | | | | | | | | | |
| H | | | | | | | | | | | | | | | | | | | | | | | | |
| J | | | | | | | | | | | | | | | | | | | | | | | | |
| K | | | | | | | | | | | | | | | | | | | | | | | | |
| L | | | | | | | | | | | | | | | | | | | | | | | | |
| M | | | | | | | | | | | | | | | | | | | | | | | | |
| N | | | | | | | | | | | | | | | | | | | | | | | | |
| P | | | | | | | | | | | | | | | | | | | | | | | | |
| Q | | | | | | | | | | | | | | | | | | | | | | | | |
| R | | | | | | | | | | | | | | | | | | | | | | | | |
| S | | | | | | | | | | | | | | | | | | | | | | | | |
| T | 135 | 139 | 140 | 137 | 145 | * | 5 | 7 | * | 17 | 19 | * | * | 31 | 29 | * | 43 | 41 | * | 54 | 62 | 60 | 59 | 64 |
| U | 136 | 144 | 141 | 138 | 146 | * | 8 | 6 | * | 20 | 18 | * | * | 30 | 32 | * | 42 | 44 | * | 53 | 61 | 55 | 58 | 63 |
| V | 149 | 147 | 142 | * | 1 | 3 | 9 | 11 | 13 | 15 | 21 | 23 | 25 | 27 | 33 | 35 | 37 | 39 | 45 | 47 | * | 52 | 57 | 50 |
| W | 150 | 148 | 143 | * | 2 | 4 | 10 | 12 | 14 | 16 | 22 | 24 | 26 | 28 | 34 | 36 | 38 | 40 | 46 | 48 | * | 51 | 56 | 49 |

NOIL2SM1300A

Table 21. PIN LIST

| Pin No. | Pin Name | Type | Direction | Description | Position |
|---------|----------|--------|-----------|-----------------------|----------|
| 1 | clkoutp | LVDS | O | p clk output channel | V5 |
| 2 | clkoutn | LVDS | O | n clk output channel | W5 |
| 3 | chp[0] | LVDS | O | p output channel [0] | V6 |
| 4 | chn[0] | LVDS | O | n output channel [0] | W6 |
| 5 | gndlvds | Supply | I/O | LVDS ground | T7 |
| 6 | gndadc | Supply | I/O | ADC ground | U8 |
| 7 | vddadc | Supply | I/O | ADC power | T8 |
| 8 | vddlvds | Supply | I/O | LVDS power | U7 |
| 9 | chp[1] | LVDS | O | p output channel [1] | V7 |
| 10 | chn[1] | LVDS | O | n output channel [1] | W7 |
| 11 | chp[2] | LVDS | O | p output channel [2] | V8 |
| 12 | chn[2] | LVDS | O | n output channel [2] | W8 |
| 13 | chp[3] | LVDS | O | p output channel [3] | V9 |
| 14 | chn[3] | LVDS | O | n output channel [3] | W9 |
| 15 | chp[4] | LVDS | O | p output channel [4] | V10 |
| 16 | chn[4] | LVDS | O | n output channel [4] | W10 |
| 17 | gndlvds | Supply | I/O | LVDS ground | T10 |
| 18 | gndadc | Supply | I/O | ADC ground | U11 |
| 19 | vddadc | Supply | I/O | ADC power | T11 |
| 20 | vddlvds | Supply | I/O | LVDS power | U10 |
| 21 | chp[5] | LVDS | O | p output channel [5] | V11 |
| 22 | chn[5] | LVDS | O | n output channel [5] | W11 |
| 23 | chp[6] | LVDS | O | p output channel [6] | V12 |
| 24 | chn[6] | LVDS | O | n output channel [6] | W12 |
| 25 | chp[7] | LVDS | O | p output channel [7] | V13 |
| 26 | chn[7] | LVDS | O | n output channel [7] | W13 |
| 27 | chp[8] | LVDS | O | p output channel [8] | V14 |
| 28 | chn[8] | LVDS | O | n output channel [8] | W14 |
| 29 | gndlvds | Supply | I/O | LVDS ground | T15 |
| 30 | gndadc | Supply | I/O | ADC ground | U14 |
| 31 | vddadc | Supply | I/O | ADC power | T14 |
| 32 | vddlvds | Supply | I/O | LVDS power | U15 |
| 33 | chp[9] | LVDS | O | p output channel [9] | V15 |
| 34 | chn[9] | LVDS | O | n output channel [9] | W15 |
| 35 | chp[10] | LVDS | O | p output channel [10] | V16 |
| 36 | chn[10] | LVDS | O | n output channel [10] | W16 |
| 37 | chp[11] | LVDS | O | p output channel [11] | V17 |
| 38 | chn[11] | LVDS | O | n output channel [11] | W17 |
| 39 | n/a | | | not assigned | V18 |
| 40 | n/a | | | not assigned | W18 |
| 41 | gndlvds | Supply | I/O | LVDS ground | T18 |
| 42 | gndadc | Supply | I/O | ADC ground | U17 |

NOIL2SM1300A

Table 21. PIN LIST

| Pin No. | Pin Name | Type | Direction | Description | Position |
|---------|---------------|--------|-----------|---|----------|
| 43 | vddadc | Supply | I/O | ADC power | T17 |
| 44 | vddlvs | Supply | I/O | LVDS power | U18 |
| 45 | clkinp | LVDS | I | LVDS input clock 315 MHz p-node | V19 |
| 46 | clkinn | LVDS | I | LVDS input clock 315 MHz n-node | W19 |
| 47 | syncp | LVDS | O | LVDS sync and output | V20 |
| 48 | syncn | LVDS | O | LVDS sync and output | W20 |
| 49 | gnddig | Supply | I/O | digital ground | W24 |
| 50 | vdddig | Supply | I/O | digital power supply | V24 |
| 51 | cap_vrefm | Analog | O | lower limit ADC range decoupling | W22 |
| 52 | cap_vrefp | Analog | O | higher limit ADC range decoupling | V22 |
| 53 | gndadc | Supply | I/O | ADC ground | U20 |
| 54 | vddadc | Supply | I/O | ADC power supply | T20 |
| 55 | gnddig | Supply | I/O | digital ground | U22 |
| 56 | gndbuf | Supply | I/O | column buffers ground | W23 |
| 57 | vddbuf | Supply | I/O | column buffers supply | V23 |
| 58 | gndana | Supply | I/O | column buffers ground | U23 |
| 59 | vddana | Supply | I/O | column buffers supply | T23 |
| 60 | vpix | Supply | I/O | pixel core supply | T22 |
| 61 | gndpix | Supply | I/O | pixel core ground | U21 |
| 62 | vsamp | Supply | I/O | image core select and sample supply | T21 |
| 63 | gndadc | Supply | I/O | ADC ground | U24 |
| 64 | vdddig | Supply | I/O | digital power supply | T24 |
| 65 | nbias_colload | Analog | O | column bias decouple | A24 |
| 66 | test_ena | CMOS | I | scan pin for sequencer; Customer: connect to ground | C24 |
| 67 | int_time1 | CMOS | I | integration pin first slope | C23 |
| 68 | int_time2 | CMOS | I | integration pin dual slope | B23 |
| 69 | int_time3 | CMOS | I | integration pin triple slope | A23 |
| 70 | monitor1 | CMOS | O | output pin for integration timing, high during integration | C22 |
| 71 | monitor2 | CMOS | O | output pin for dual slope integration timing, high during integration | B22 |
| 72 | monitor3 | CMOS | O | output pin for triple slope integration timing, high during integration | A22 |
| 73 | cap_vrefadc | Analog | O | ADC black reference decoupling | C21 |
| 74 | vpix | Supply | I/O | pixel core supply | B21 |
| 75 | cap_vrefcm | Analog | O | ADC common mode decoupling | A21 |
| 76 | reset_n | CMOS | I/O | chip reset (active low) | C20 |
| 77 | scan_en | CMOS | I | DFT scan enable; Customer: connect to ground | B20 |
| 78 | scan_clk | CMOS | I | DFT clock; Customer: connect to ground | A20 |
| 79 | scan_clk_en | CMOS | I | DFT clock enable; Customer: connect to ground | C19 |
| 80 | gndpix | Supply | I/O | pixel core ground | B19 |
| 81 | gnddig | Supply | I/O | digital ground | A19 |
| 82 | vdddig | Supply | I/O | digital power supply | C18 |

NOIL2SM1300A

Table 21. PIN LIST

| Pin No. | Pin Name | Type | Direction | Description | Position |
|---------|----------|--------|-----------|---|----------|
| 83 | vpix | Supply | I/O | pixel core supply | B18 |
| 84 | pixdiode | Analog | O | pixel diode current pin; Customer: keep it floating | A18 |
| 85 | gndpix | Supply | I/O | pixel core ground | C17 |
| 86 | vsamp | Supply | I/O | image core select and sample supply | B17 |
| 87 | vresetab | Supply | I/O | anti blooming lower reset level | A17 |
| 88 | vprech | Supply | I/O | pixel precharge level/decoupling pin | C16 |
| 89 | vmemh | Supply | I/O | pixel memory reference high | B16 |
| 90 | vmeml | Supply | I/O | pixel memory reference low | A16 |
| 91 | vreset | Supply | I/O | pixel reset level | C15 |
| 92 | vresetds | Supply | I/O | pixel dual slope reset level/decoupling pin | B15 |
| 93 | vresetts | Supply | I/O | pixel triple slope reset level/decoupling pin | A15 |
| 94 | vresetab | Supply | I/O | anti blooming lower reset level | C14 |
| 95 | gndpix | Supply | I/O | pixel core ground | B14 |
| 96 | vresetts | Supply | I/O | pixel triple slope reset level/decoupling pin | A14 |
| 97 | vresetds | Supply | I/O | pixel dual slope reset level/decoupling pin | C13 |
| 98 | vreset | Supply | I/O | pixel reset level | B13 |
| 99 | vsamp | Supply | I/O | image core select and sample supply | A13 |
| 100 | vmeml | Supply | I/O | pixel memory reference low | A12 |
| 101 | vmemh | Supply | I/O | pixel memory reference high | B12 |
| 102 | vprech | Supply | I/O | pixel precharge level/decoupling pin | C12 |
| 103 | n/a | | | not assigned | A11 |
| 104 | gndpix | Supply | I/O | pixel core ground | B11 |
| 105 | vresetab | Supply | I/O | anti blooming lower reset level | C11 |
| 106 | vresetts | Supply | I/O | pixel triple slope reset level/decoupling pin | A10 |
| 107 | vresetds | Supply | I/O | pixel dual slope reset level/decoupling pin | B10 |
| 108 | vreset | Supply | I/O | pixel reset level | C10 |
| 109 | vmeml | Supply | I/O | pixel memory reference low | A9 |
| 110 | vmemh | Supply | I/O | pixel memory reference high | B9 |
| 111 | vprech | Supply | I/O | pixel precharge level/decoupling pin | C9 |
| 112 | vresetab | Supply | I/O | anti blooming lower reset level | A8 |
| 113 | vsamp | Supply | I/O | image core select and sample supply | B8 |
| 114 | gndpix | Supply | I/O | pixel core ground | C8 |
| 115 | ibiaspre | Analog | I | external current bias for vprech (not connected by default); Customer: connect with 0.1 μ f to ground | A7 |
| 116 | vpix | Supply | I/O | pixel core supply | B7 |
| 117 | vdddig | Supply | I/O | digital power supply | C7 |
| 118 | gnddig | Supply | I/O | digital ground | A6 |
| 119 | gndpix | Supply | I/O | pixel core ground | B6 |
| 120 | n/a | | | not assigned | C6 |
| 121 | n/a | | | not assigned | A5 |
| 122 | n/a | | | not assigned | B5 |
| 123 | n/a | | | not assigned | C5 |

NOIL2SM1300A

Table 21. PIN LIST

| Pin No. | Pin Name | Type | Direction | Description | Position |
|---------|-------------|--------|-----------|---|----------|
| 124 | cap_vrefcm | Analog | O | ADC common mode decoupling | A4 |
| 125 | vpix | Supply | I/O | pixel core supply | B4 |
| 126 | cap_vrefadc | Analog | O | ADC black reference decoupling | C4 |
| 127 | spics | CMOS | I | SPI chip select | A3 |
| 128 | spiclk | CMOS | I | SPI clock | B3 |
| 129 | spiin | CMOS | I | SPI serial input | C3 |
| 130 | spiout | CMOS | O | SPI serial output | A2 |
| 131 | mbsbus[0] | Analog | I/O | first mixed boundary scan bus; Customer: keep it floating | B2 |
| 132 | mbsbus[1] | Analog | I/O | second mixed boundary scan bus; Customer: keep it floating | C2 |
| 133 | refbg | Analog | I/O | external bias resistor; Customer: connect with 47 kΩ to ground | C1 |
| 134 | cmdmbs | Analog | I | bias current for mbs buffers; Customer: connect with 0.1 μf to ground | A1 |
| 135 | vdddig | Supply | I/O | digital power supply | T1 |
| 136 | gndadc | Supply | I/O | ADC ground | U1 |
| 137 | vsamp | Supply | I/O | image core select and sample supply | T4 |
| 138 | gndpix | Supply | I/O | pixel core ground | U4 |
| 139 | vpix | Supply | I/O | pixel core supply | T2 |
| 140 | vddana | Supply | I/O | analog power supply | T3 |
| 141 | gndana | Supply | I/O | analog ground | U3 |
| 142 | vddbbuf | Supply | I/O | column buffers supply | V3 |
| 143 | gndbuf | Supply | I/O | column buffers ground | W3 |
| 144 | gnddig | Supply | I/O | digital ground | U2 |
| 145 | vddadc | Supply | I/O | ADC power supply | T5 |
| 146 | gndadc | Supply | I/O | ADC ground | U5 |
| 147 | cap_vrefp | Analog | I/O | higher limit ADC range decoupling | V2 |
| 148 | cap_vrefm | Analog | I/O | lower limit ADC range decoupling | W2 |
| 149 | vdddig | Supply | I/O | digital power supply | V1 |
| 150 | gnddig | Supply | I/O | digital ground | W1 |

NOIL2SM1300A

Table 22. MECHANICAL SPECIFICATIONS

| Parameter | Description | Min | Typ | Max | Units |
|--|--|---------------------------------------|-------------|------|-------|
| Die (Pin 1 is located bottom left) | Die thickness | NA | 750 | NA | μm |
| | Die position, X offset to the package center | NA | -42 | NA | μm |
| | Die position, Y offset to the package center | NA | -150 | NA | μm |
| | Die position, X tilt | -1 | 0 | 1 | deg |
| | Die position, Y tilt | -1 | 0 | 1 | deg |
| | Die placement accuracy in package | -50 | 0 | 50 | μm |
| | Die rotation accuracy | -1 | 0 | 1 | deg |
| | Optical center referenced from the die center (X-dir) | NA | -121 | NA | μm |
| | Optical center referenced from the die center (Y-dir) | NA | +2280 | NA | μm |
| | Distance from PCB plane to top of the die surface | NA | 1.75 | NA | mm |
| | Distance from top of the die surface to top of the glass lid | NA | 1.15 | NA | mm |
| Glass Lid | XY size | NA | 27.4 x 27.4 | NA | mm |
| | Thickness | NA | 0.9 | NA | mm |
| | Spectral range for optical coating of window | 400 | - | 1100 | nm |
| | Reflection coefficient for window (refer to Figure 36) | NA | <0.8 | NA | % |
| Mechanical Shock | JESD22-B104C; Condition G | NA | 2000 | NA | G |
| Vibration | JESD22-B103B; Condition 1 | 20 | - | 2000 | Hz |
| Mounting Profile | Pb-free wave soldering profile for pin grid array package if no socket is used | | | | |
| Recommended Socket Manufacturer | Andon Electronics (www.andonelectronics.com) | BGA Socket: 10-24-05-168-319T-P27-L14 | | | |
| | | Thru Hole: 10-24-05-168-347T-P27-L14 | | | |

Glass Lid

The LUPA1300-2 monochrome and color image sensor uses a glass lid without any coatings. Figure 36 shows the transmission characteristics of the glass lid.

As shown in Figure 36, no infrared attenuating color filter glass is used. A filter must be provided in the optical path when color devices are used (source: <http://www.pgo-online.com>).

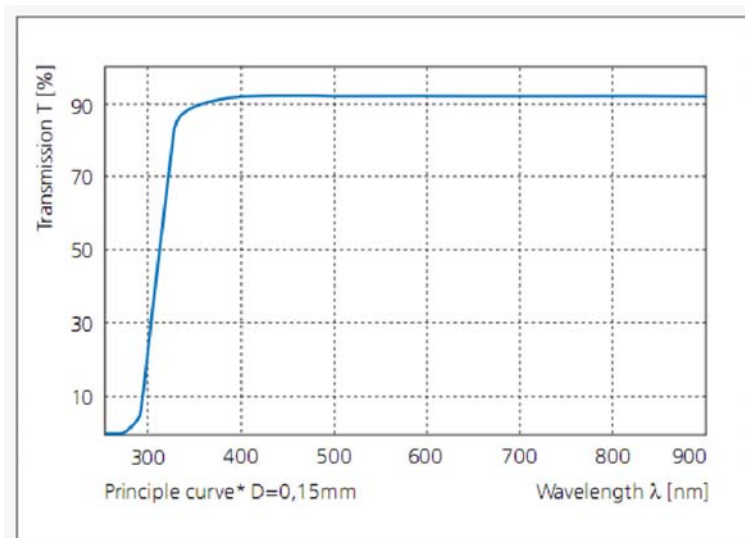


Figure 36. Transmission Characteristics of the Glass Lid

SPECIFICATIONS AND USEFUL REFERENCES

Specifications, Application Notes and useful resources can be accessed via customer login account at MyON – CISP Extranet.

<https://www.onsemi.com/PowerSolutions/myon/erCispFol der.do>

Useful References

For information on ESD and cover glass care and cleanliness, please download the *Image Sensor Handling and Best Practices* Application Note (AN52561/D) from www.onsemi.com.

For quality and reliability information, please download the *Quality & Reliability Handbook* (HBD851/D) from www.onsemi.com.

For information on Standard terms and Conditions of Sale, please download [Terms and Conditions](http://www.onsemi.com) from www.onsemi.com.

Product Application Notes

- AN54468: Interfacing the LUPA1300-2 with FPGA

This application note describes the interface between the LUPA1300-2 and the FPGA, as implemented in the LUPA1300-2 demonstration kit. It also provides an overview of the architecture of the demonstration kit and the method used to synchronize channels.

- AN54214: High Speed Layout Guidelines for the LUPA1300-2 Image Sensor

- AN54598: Pixel Remapping Implementation in LUPA1300-2 Demonstration Kit

This application note explains the remapping technique implemented in LUPA1300-2 demonstration system to align non consecutive pixels readout to consecutive pixels for creating proper images. It also describes the remapping method during Reverse-X/Y readout and subsampling modes of operation.

Acceptance Criteria Specification

The Product Acceptance Criteria is available on request. This document contains the criteria to which the LUPA1300-2 is tested before being shipped.

Return Material Authorization (RMA)

Refer to the ON Semiconductor RMA policy procedure at http://www.onsemi.com/site/pdf/CAT_Returns_FailureAnalysis.pdf

NOIL2SM1300A

ACRONYMS

| Acronym | Description |
|---------|---|
| ADC | Analog-to-Digital Converter |
| AFE | Analog Front End |
| BL | Black pixel data |
| CDM | Charged Device Model |
| CDS | Correlated Double Sampling |
| CMOS | Complementary Metal Oxide Semiconductor |
| CRC | Cyclic Redundancy Check |
| DAC | Digital-to-Analog Converter |
| DDR | Double Data Rate |
| DNL | Differential Non-Linearity |
| DS | Double Sampling |
| DSNU | Dark Signal Non-Uniformity |
| EIA | Electronic Industries Alliance |
| ESD | Electrostatic Discharge |
| FE | Frame End |
| FF | Fill Factor |
| FOT | Frame Overhead Time |
| FPGA | Field Programmable Gate Array |
| FPN | Fixed Pattern Noise |
| FPS | Frames per Second |
| FS | Frame Start |
| HBM | Human Body Model |
| IMG | Image data (regular pixel data) |
| INL | Integral Non-Linearity |

| Acronym | Description |
|----------------|---|
| IP | Intellectual Property |
| LE | Line End |
| LS | Line Start |
| LSB | Least Significant Bit |
| LVDS | Low-Voltage Differential Signaling |
| MSB | Most Significant Bit |
| PGA | Programmable Gain Amplifier |
| PLS | Parasitic Light Sensitivity |
| PRBS | Pseudo-Random Binary Sequence |
| PRNU | Pixel Random Non-Uniformity |
| QE | Quantum Efficiency |
| RGB | Red-Green-Blue |
| RMA | Return Material Authorization |
| RMS | Root Mean Square |
| ROI | Region of Interest |
| ROT | Row Overhead Time |
| S/H | Sample and Hold |
| SNR | Signal-to-Noise Ratio |
| SPI | Serial Peripheral Interface |
| TIA | Telecommunications Industry Association |
| T _J | Junction Temperature |
| TR | Training Pattern |
| % RH | Percent Relative Humidity |

GLOSSARY

| | |
|-------------------|--|
| conversion gain | A constant that converts the number of electrons collected by a pixel into the voltage swing of the pixel. Conversion gain = q/C where q is the charge of an electron (1.602×10^{-19} Coulomb) and C is the capacitance of the photodiode or sense node. |
| CDS | Correlated double sampling. This is a method for sampling a pixel where the pixel voltage after reset is sampled and subtracted from the voltage after exposure to light. |
| CFA | Color filter array. The materials deposited on top of pixels that selectively transmit color. |
| DNL | Differential nonlinearity (for ADCs) |
| DSNU | Dark signal nonuniformity. This parameter characterizes the degree of nonuniformity in dark leakage currents, which can be a major source of fixed pattern noise. |
| fill-factor | A parameter that characterizes the optically active percentage of a pixel. In theory, it is the ratio of the actual QE of a pixel divided by the QE of a photodiode of equal area. In practice, it is never measured. |
| INL | Integral nonlinearity (for ADCs) |
| IR | Infrared. IR light has wavelengths in the approximate range 750 nm to 1 mm. |
| Lux | Photometric unit of luminance (at 550 nm, $1 \text{ lux} = 1 \text{ lumen/m}^2 = 1/683 \text{ W/m}^2$) |
| pixel noise | Variation of pixel signals within a region of interest (ROI). The ROI typically is a rectangular portion of the pixel array and may be limited to a single color plane. |
| photometric units | Units for light measurement that take into account human physiology. |
| PLS | Parasitic light sensitivity. Parasitic discharge of sampled information in pixels that have storage nodes. |
| PRNU | Photo-response nonuniformity. This parameter characterizes the spread in response of pixels, which is a source of FPN under illumination. |
| QE | Quantum efficiency. This parameter characterizes the effectiveness of a pixel in capturing photons and converting them into electrons. It is photon wavelength and pixel color dependent. |
| read noise | Noise associated with all circuitry that measures and converts the voltage on a sense node or photodiode into an output signal. |
| reset | The process by which a pixel photodiode or sense node is cleared of electrons. "Soft" reset occurs when the reset transistor is operated below the threshold. "Hard" reset occurs when the reset transistor is operated above threshold. |
| reset noise | Noise due to variation in the reset level of a pixel. In 3T pixel designs, this noise has a component (in units of volts) proportionality constant depending on how the pixel is reset (such as hard and soft). In 4T pixel designs, reset noise can be removed with CDS. |
| responsivity | The standard measure of photodiode performance (regardless of whether it is in an imager or not). Units are typically A/W and are dependent on the incident light wavelength. Note that responsivity and sensitivity are used interchangeably in image sensor characterization literature so it is best to check the units. |
| ROI | Region of interest. The area within a pixel array chosen to characterize noise, signal, crosstalk, and so on. The ROI can be the entire array or a small subsection; it can be confined to a single color plane. |
| sense node | In 4T pixel designs, a capacitor used to convert charge into voltage. In 3T pixel designs it is the photodiode itself. |
| sensitivity | A measure of pixel performance that characterizes the rise of the photodiode or sense node signal in Volts upon illumination with light. Units are typically $\text{V}/(\text{W}/\text{m}^2)/\text{sec}$ and are dependent on the incident light wavelength. Sensitivity measurements are often taken with 550 nm incident light. At this wavelength, 1 683 lux is equal to $1 \text{ W}/\text{m}^2$; the units of sensitivity are quoted in $\text{V}/\text{lux}/\text{sec}$. Note that responsivity and sensitivity are used interchangeably in image sensor characterization literature so it is best to check the units. |
| spectral response | The photon wavelength dependence of sensitivity or responsivity. |
| SNR | Signal-to-noise ratio. This number characterizes the ratio of the fundamental signal to the noise spectrum up to half the Nyquist frequency. |
| temporal noise | Noise that varies from frame to frame. In a video stream, temporal noise is visible as twinkling pixels. |

MECHANICAL CASE OUTLINE

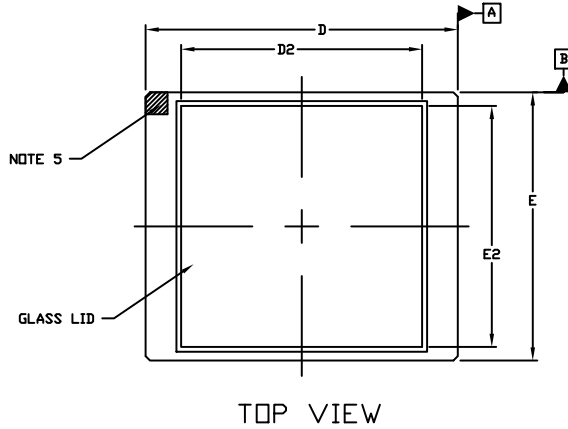
PACKAGE DIMENSIONS

ON Semiconductor®



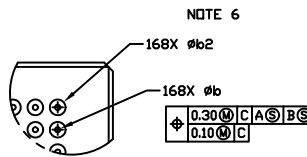
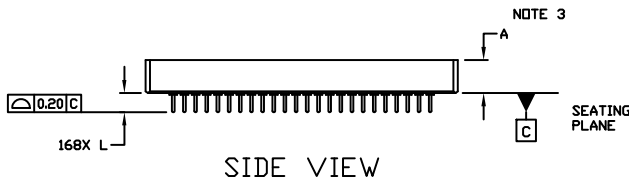
CPGA168, 35.50x30.50
CASE 107DH-01
ISSUE O

DATE 30 JUN 2011



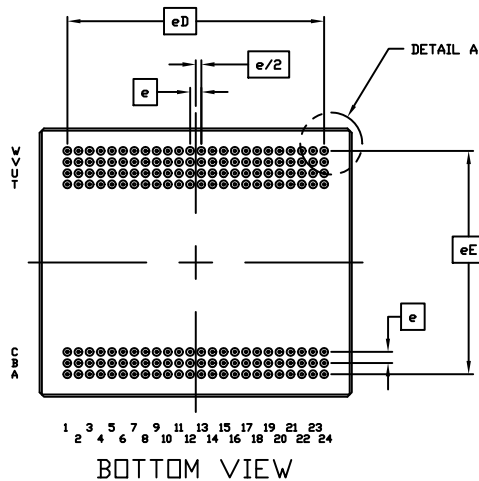
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION A INCLUDES THE PACKAGE BODY AND LID BUT DOES NOT INCLUDE HEATSINKS OR OTHER ATTACHED FEATURES.
4. DIMENSIONS D AND E DO NOT INCLUDE PROTRUSIONS. SUCH PROTRUSIONS SHALL NOT EXTEND MORE THAN 0.08 ON ANY SIDE. CORNERS AND EDGES OF THE PACKAGE MAY HAVE CHAMFERS.
5. PIN A1 IDENTIFICATION WILL BE IN THIS AREA. ID TYPE MAY CONSIST OF NOTCHES, METALLIZED MARKINGS, OR OTHER FEATURES.
6. THIS DIMENSION DEFINES THE MAXIMUM SIZE FOR THE PIN BRAZE PADS.



DETAIL A
2X SCALE

| DIM | MILLIMETERS | |
|-----|-------------|-------|
| | MIN. | MAX. |
| A | 3.37 | 4.13 |
| b | 0.25 | 0.35 |
| b2 | --- | 0.95 |
| D | 35.14 | 35.86 |
| D2 | 27.40 | REF |
| E | 30.19 | 30.81 |
| E2 | 27.40 | REF |
| e | 1.27 | BSC |
| eD | 29.21 | BSC |
| eE | 25.40 | BSC |
| L | 1.83 | 2.23 |

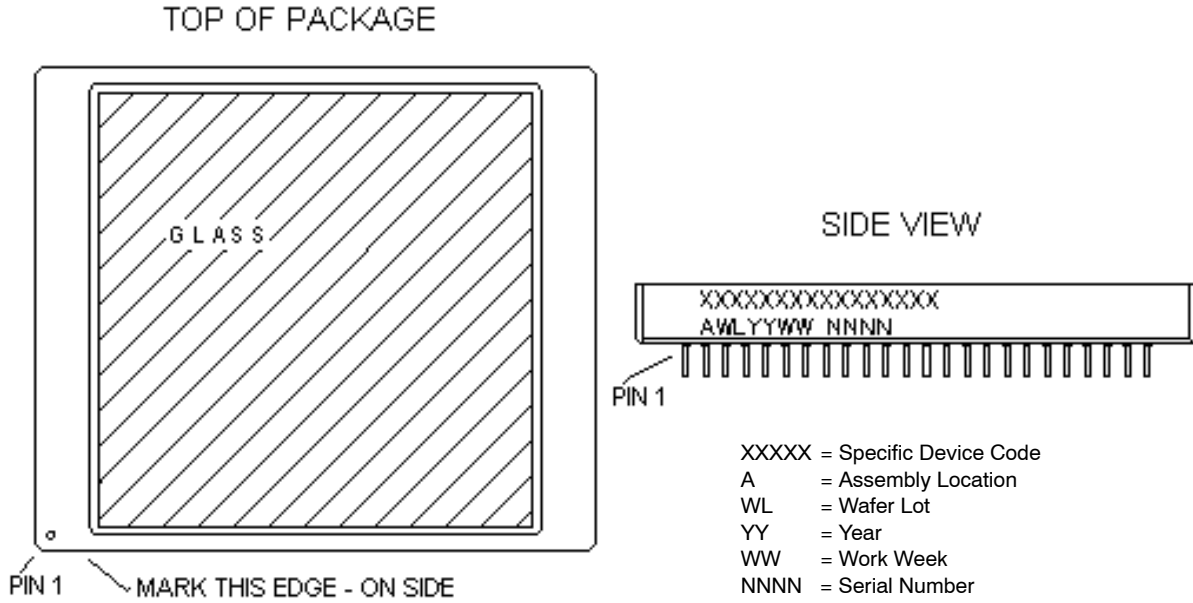


GENERIC MARKING
DIAGRAM ON PAGE 2


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| DESCRIPTION: | CPGA168, 35.50 X 30.50 | PAGE 1 OF 2 |

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**GENERIC
MARKING DIAGRAM**



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| DESCRIPTION: | CPGA168, 35.50 X 30.50 | PAGE 2 OF 2 |

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